



# LGAD R&D Status & Future

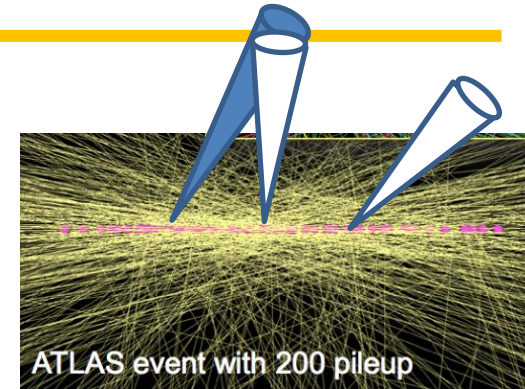
Koji Nakamura

Sayuka Kita, Tomoka Imamura,  
Ikumi Goya, Kazuhiko Hara

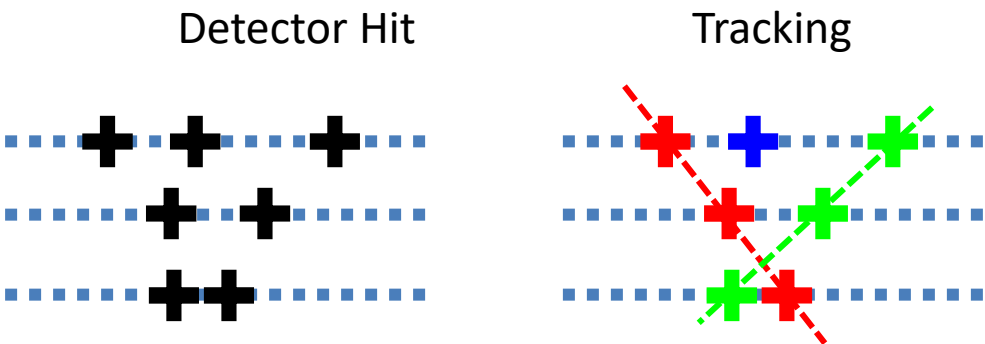


# Tracking detector with timing resolution

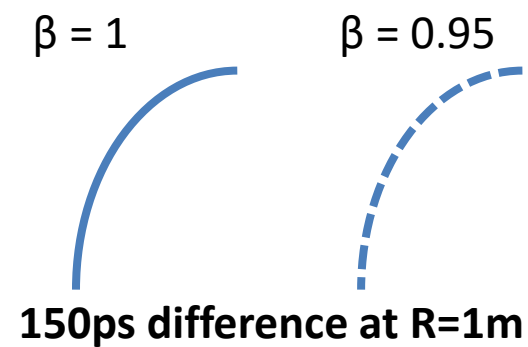
- Collider experiment gets high energy and high intensity.
  - Solving pileup issue is required for tracking, **Timing resolution helps!**
  - **Future Tracking detector should have timing information for all hits!**
- Tentative Requirement
  - **30ps timing resolution**
  - **~o(10)um spatial resolution (Pixel type).**
  - (hadron collider) **~o(10<sup>16</sup>)n<sub>eq</sub>/cm<sup>2</sup> radiation tolerance**



## 4D tracking !

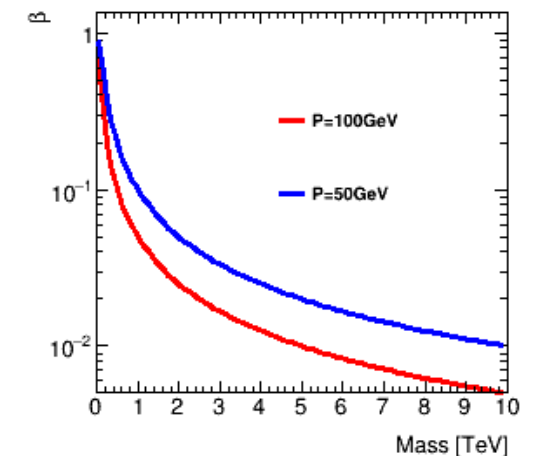


## Particle identification



K+  $\pi^+$  separation

## Mass spectrum for new particle



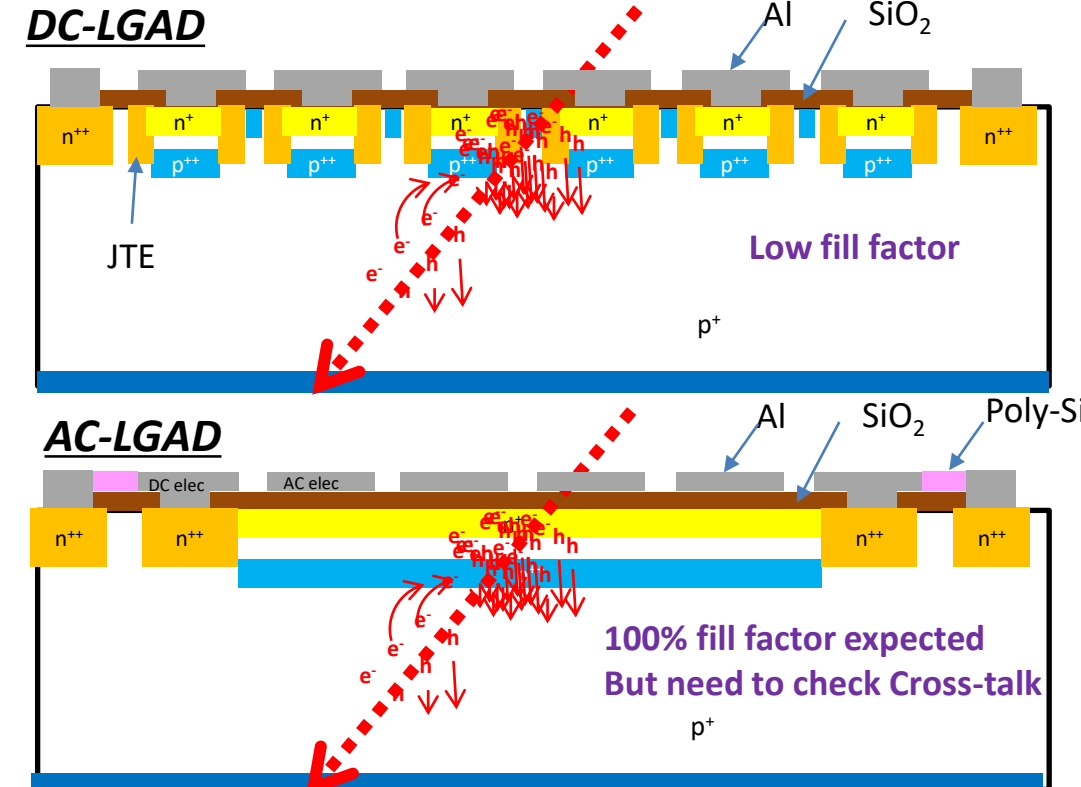
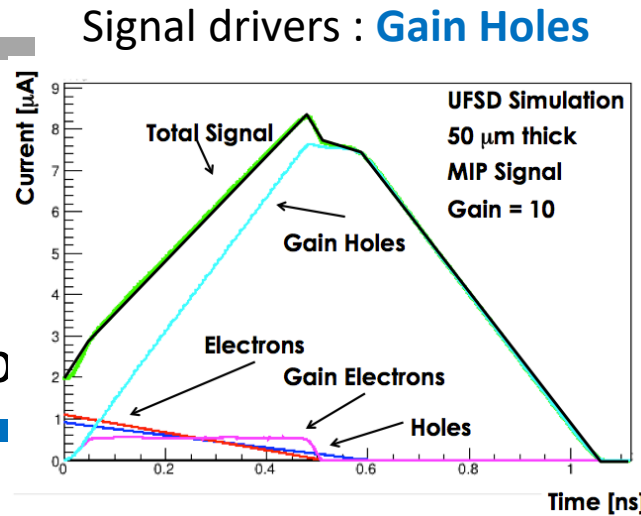
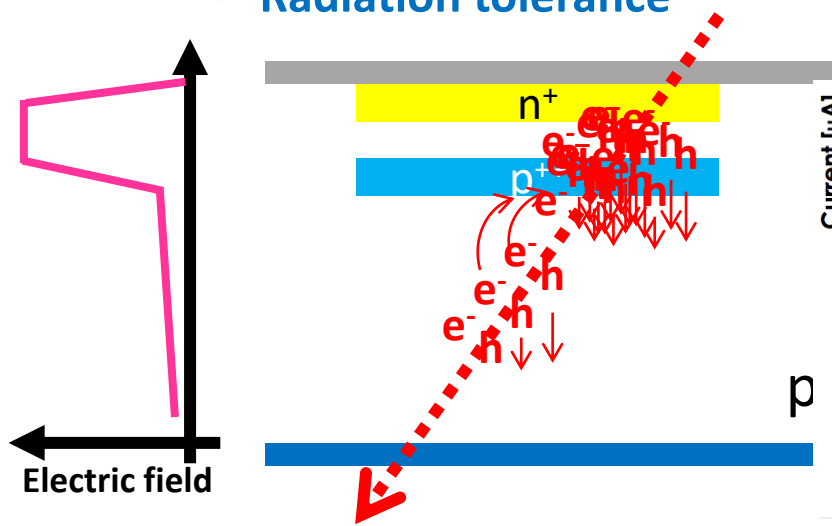
$\beta$  measurement to obtain mass

e.g. Mass measurement for Long lived chargino

# LGAD detector and spatial resolution (AC-LGAD)

- Low gain Avalanche Diode (LGAD)
  - General  $n^+$ -in- $p$  type sensor with  $p^+$  gain layer under  $n^+$  implant to make higher Electric Field
  - Good timing resolution.
  - **30ps timing resolution achieved already in 2015.**
  - R&D topics
    - **Finer electrode separation for spatial resolution**
    - **Radiation tolerance**

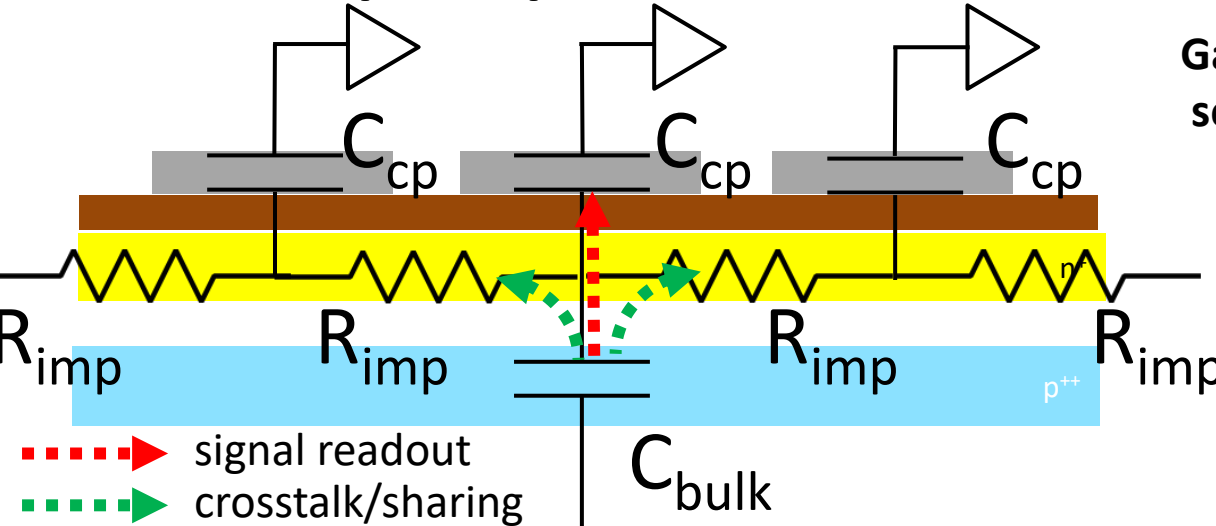
- Limitation of LGAD :
  - Need JTE and p-stop structure to have individual gain layer → **Low fill factor (20% for 80um strip)**
- AC-LGAD :
  - **Uniform gain layer with AC-Coupled electrode. 100% fill factor. Signal shared on neighboring electrodes.**



**For finer electrode LGAD, Gain Uniformity is extremely important and no other way possible.**

# AC-LGAD detector

## Read out principle of AC-LGAD

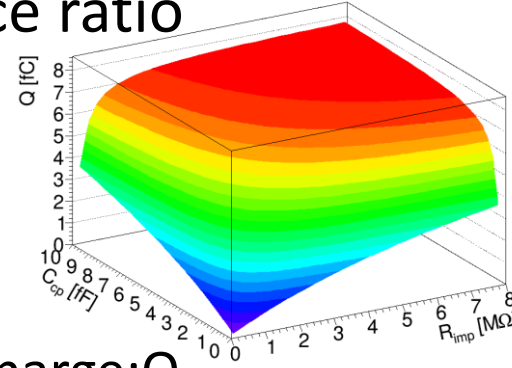


## Charge split : Impedance ratio

Assuming  $Z_{C_{bulk}} \gg Z_{C_{cp}}$ ...

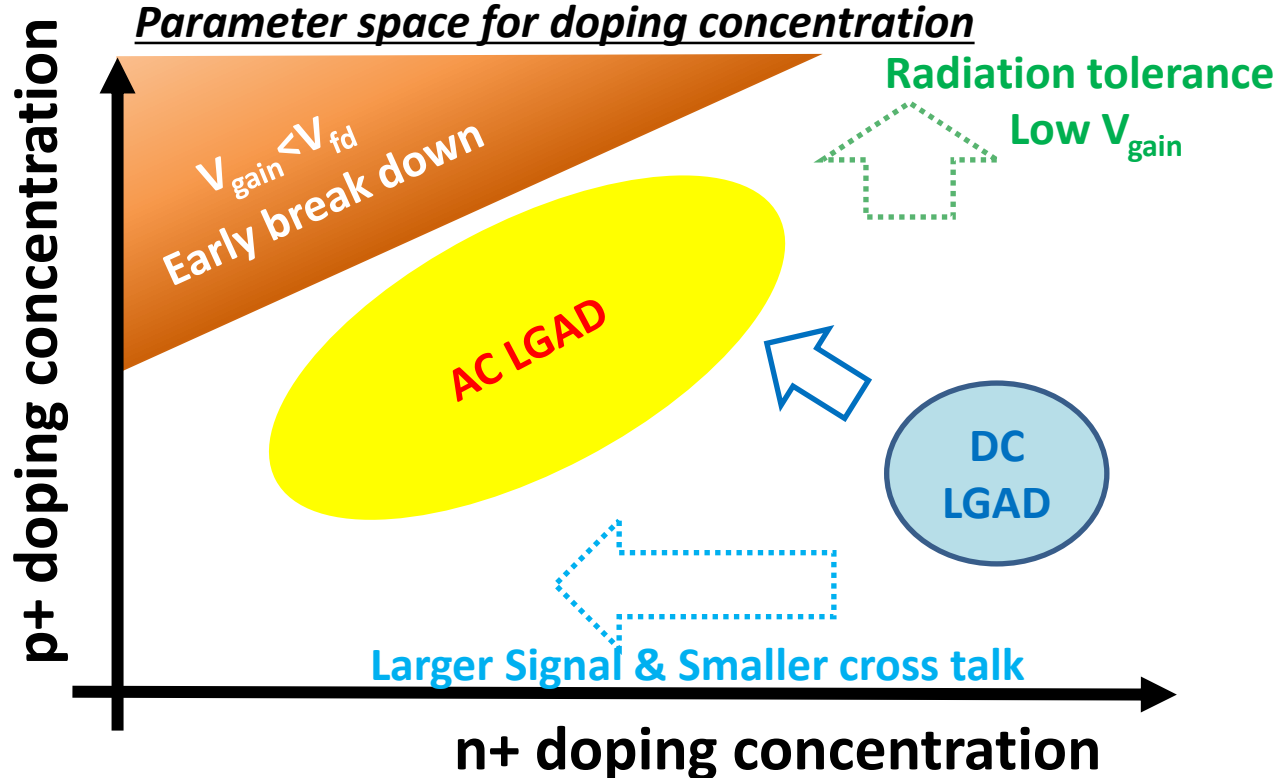
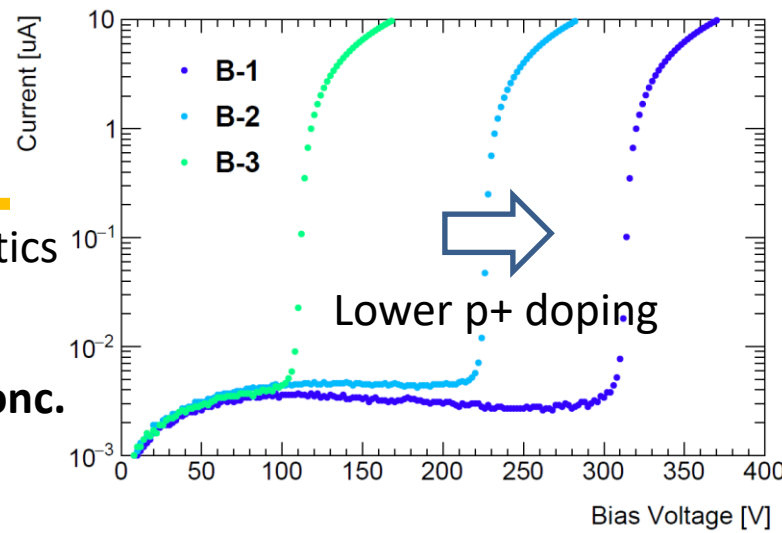
$$Q = \frac{Z_{R_{imp}}}{Z_{R_{imp}} + Z_{C_{cp}}} Q_0$$

- Amount of produced charge:  $Q_0$
- Readout Charge :  $Q$



I-V characteristics

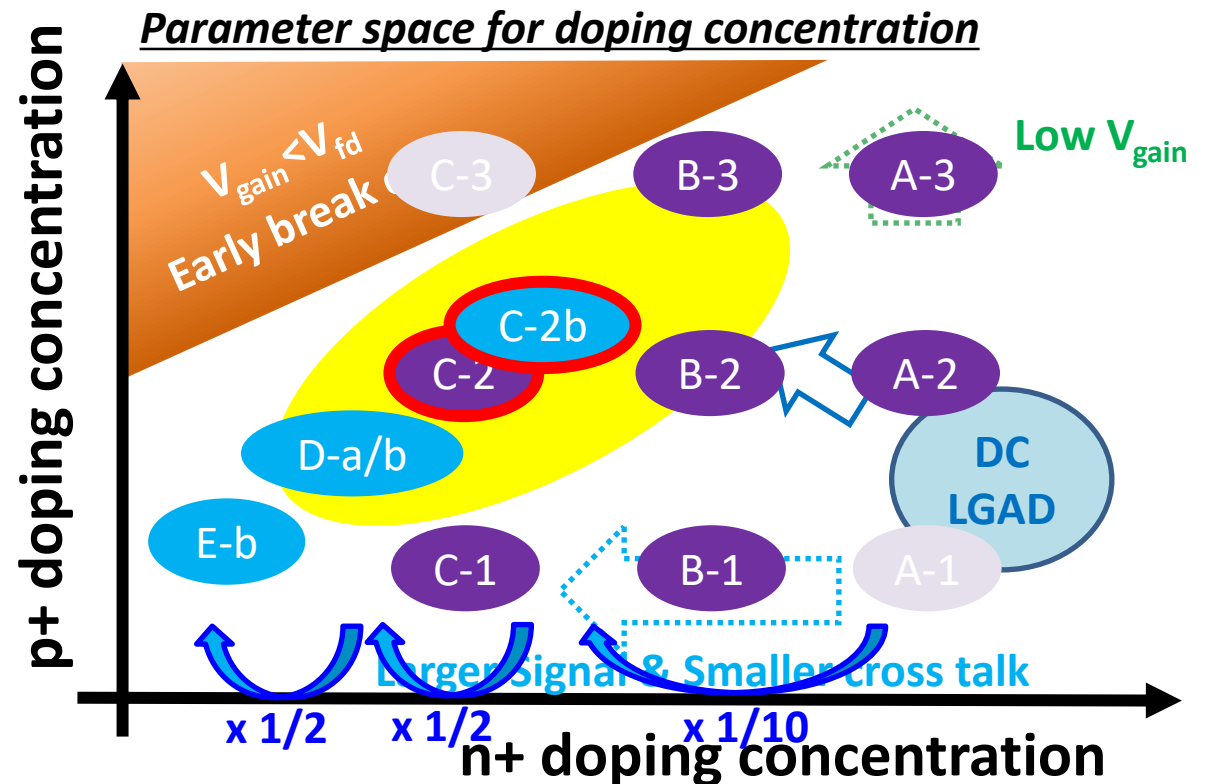
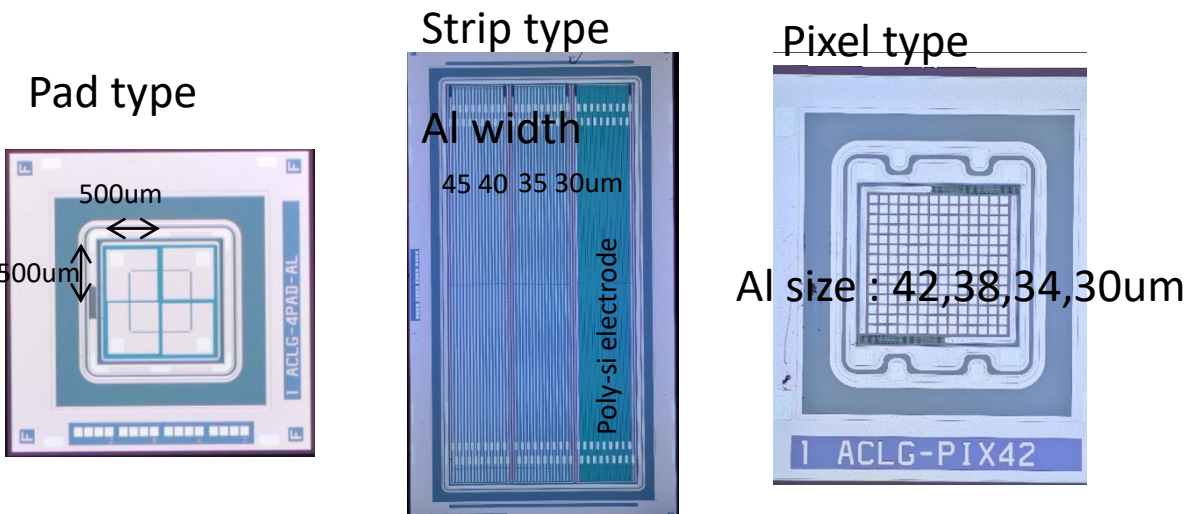
Gain Voltage ( $V_{gain}$ ) is quite sensitive to the p+ doping conc.



# HPK LGAD development

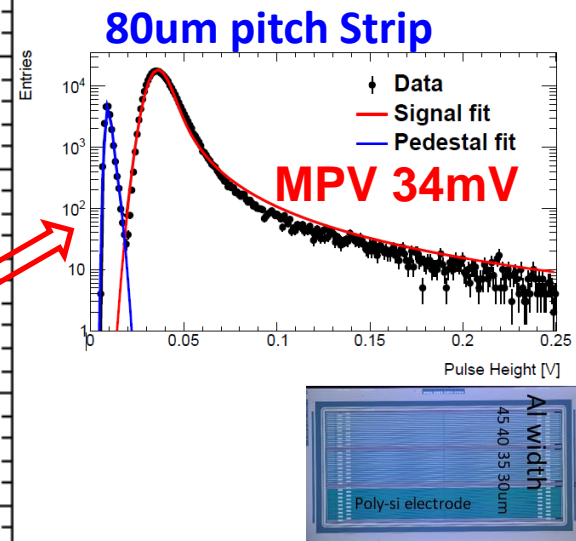
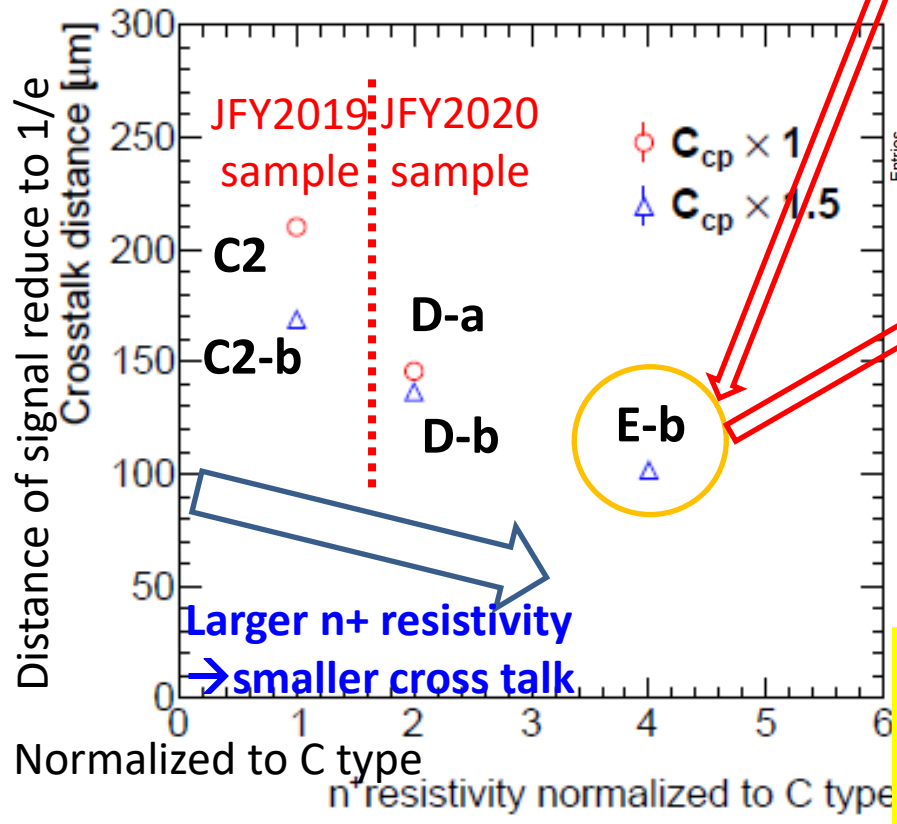
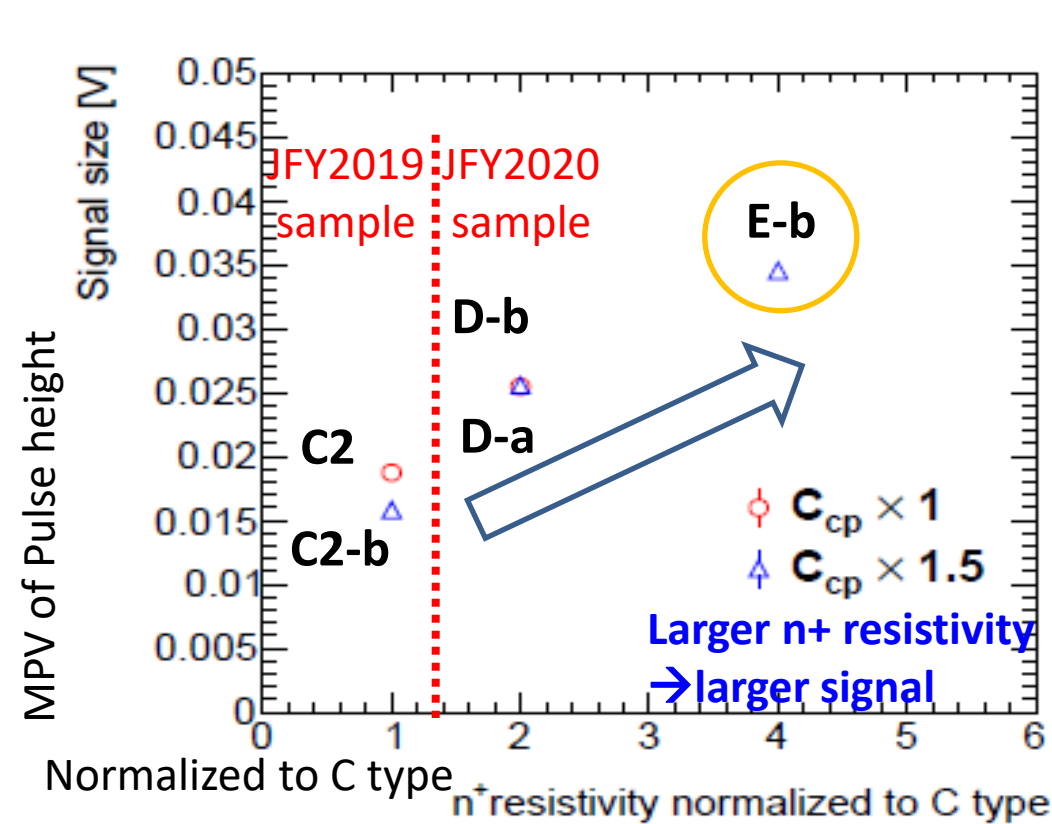
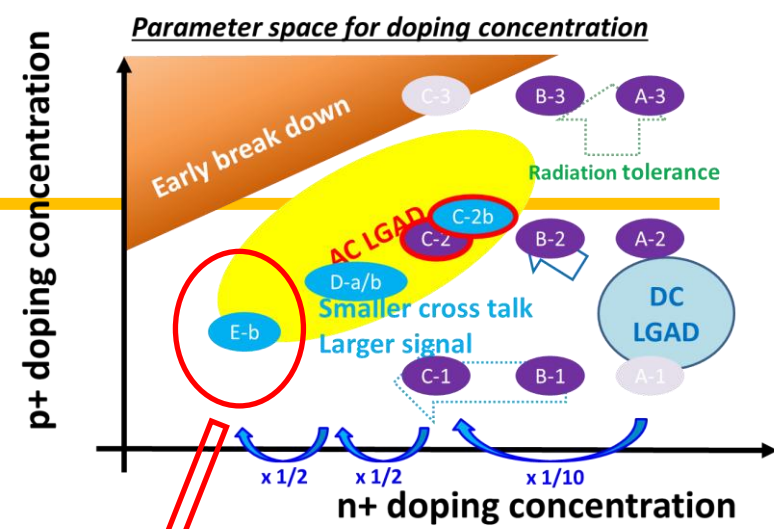
- JFY2015-JFY2018 DC-LGAD
  - **We contributed only first prototype.** HGTD took over.
- JFY2019, JFY2020 AC-LGAD production Run I
  - Vary n+ and p+ dope (A-E, 1-3)
  - Vary thickness of SiO<sub>2</sub> (capacitance : C<sub>b</sub>=1.5xC<sub>a</sub>)
- Electrode type
  - Pad type: 500um sq. 4pad/sensor
  - **Strip type : 80um pitch**
  - Pixel type : 50um sq. 14x14 electrode

- JFY2019 Samples
- JFY 2020 Samples
- ➔ Evaluated JFY2021



# Signal size and crosstalk

- **80um pitch Strip type** : Signal size and Crosstalk
  - n+ resistivity dependence of signal size and crosstalk.
  - **Large n+ resistivity → Large signal & Smaller crosstalk**



Successfully developed Good S/N 80um pitch strip detector!

# Signal size and crosstalk

Submitted to NIM A in July 2022 <https://arxiv.org/abs/2207.07355>

**Optimization of capacitive coupled Low Gain Avalanche Diode (AC-LGAD) sensors for precise time and spatial resolution**

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**Abstract**

Capacitive-coupled Low-Gain Avalanche Diode (AC-LGAD) sensors are being developed for high-energy particle physics experiments as a detector which provides fast time information with fine spatial resolution. This paper describes optimizations of AC-LGAD sensor fabrication parameters, such as doping concentrations of the gain and electrode layers as well as the AC insulator capacitance, to realize  $\mathcal{O}(10)$   $\mu\text{m}$  spacial resolution, small charge cross talk to the neighboring electrodes, detection efficiency higher than 99% at a  $10^{-4}$  fake rate and time resolution of about 30 ps. The radiation tolerance of the sensor is presented. In addition, further application to a device capable of visible and infra-red light detection is discussed.

**Keywords:** silicon tracker, LGAD, AC-LGAD, time and spatial resolution

**1. Introduction**

Particle detectors at future lepton or hadron colliders will require to cover a very large area by a tracker with fine spatial resolution of  $\mathcal{O}(10)$   $\mu\text{m}$ . A timing capability of  $\mathcal{O}(10)$  ps in addition should improve the tracking reconstruction. Precise time information is particularly inevitable in conditions where high particle density is a consequence of large multiple interactions caused by intense beam-bunch collisions. Also time can help in particle identification of charged particles, separating such between  $K/\pi$  mesons and protons. It has been evaluated that equipping the HL-LHC ATLAS detector with 30 ps precision timing devices is significant, resulting in up to 20% of improvement in the pileup vertices rejection [1], which translates into a significant cost saving due to reduction in the accelerator run-time.

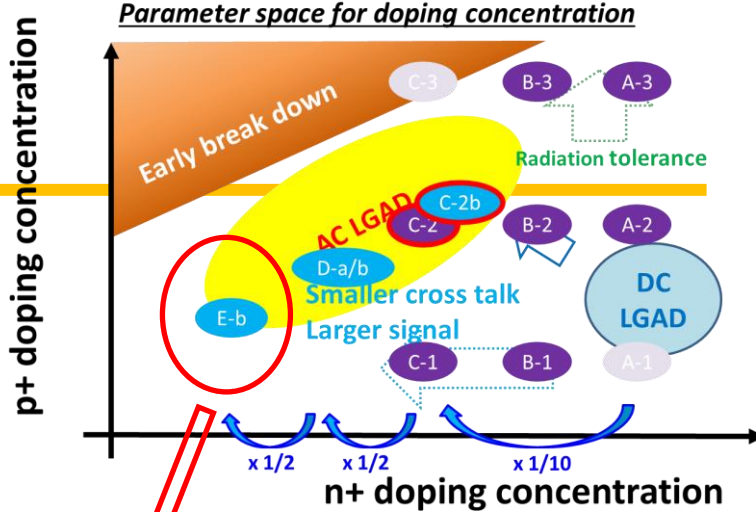
laboratory measurement system and in 800 MeV electron beam. The samples were also irradiated by  $^{60}\text{Co}$   $\gamma$  rays and by 70 MeV protons for radiation tolerance studies.

**2. LGAD sensors**

The LGAD technology has now become a mature technology and 30 ps time resolution is achievable. In this section, LGAD sensor design and improvement of granularity using AC-LGAD technology are described.

**2.1. LGAD sensor and spatial resolution**

The LGAD sensor is basically an  $n^+$ -in- $p$  semiconductor diode, containing an additional  $p^+$  layer under the  $n^+$  electrodes with a larger boron doping compared to that in the  $p$ -bulk region. The additional layer makes an extremely



80um pitch

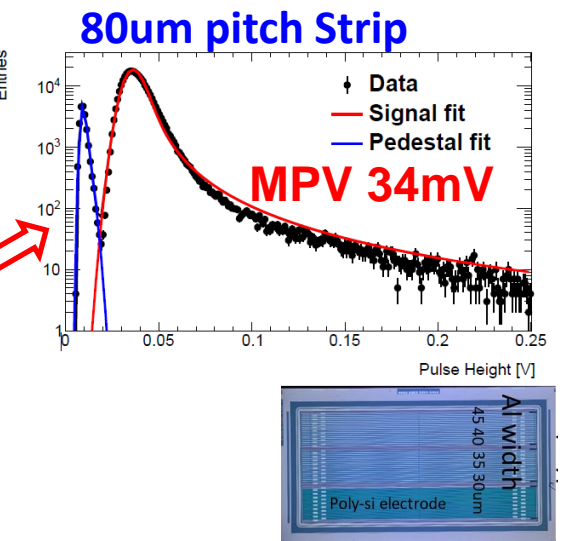
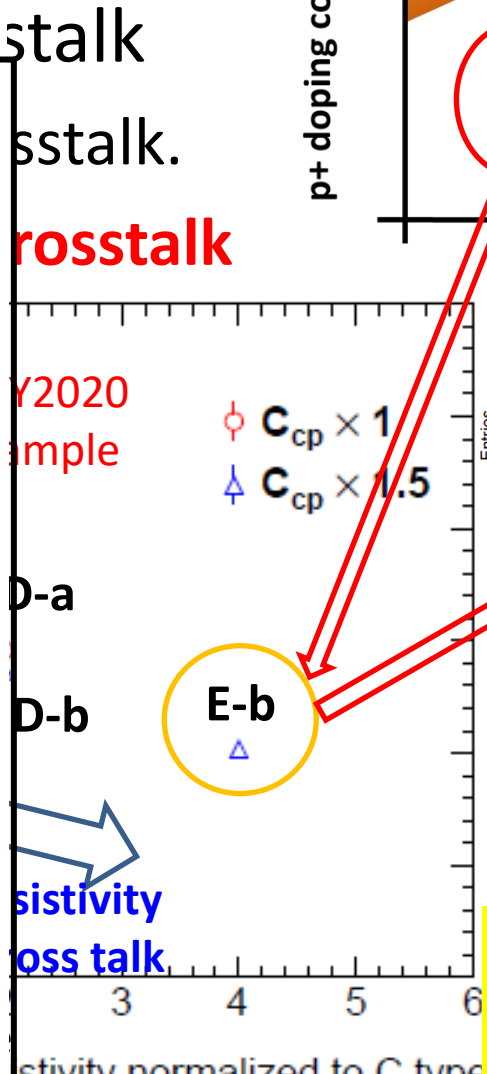
n+ re

Larg

Signal size [M]

MPV of Pulse height

Normalized to



Successfully developed Good S/N 80um pitch strip detector!

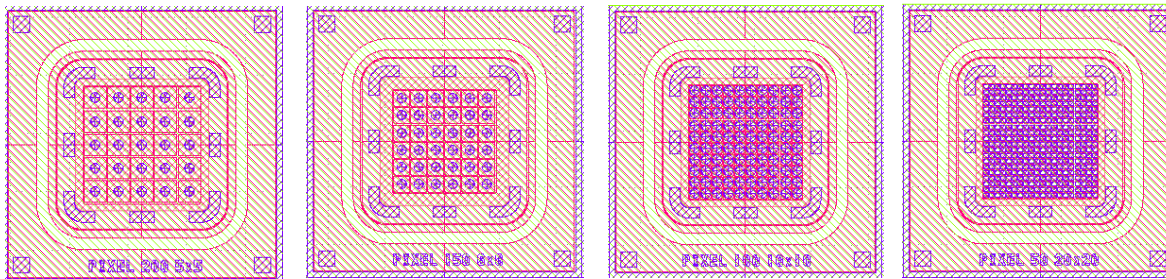
# AC-LGAD run II (2021 sample) : in April 2022

Used thinner di-electric layer (Oxide layer)

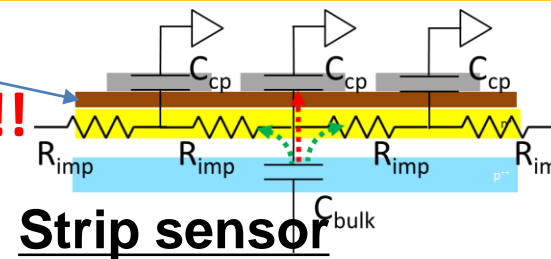
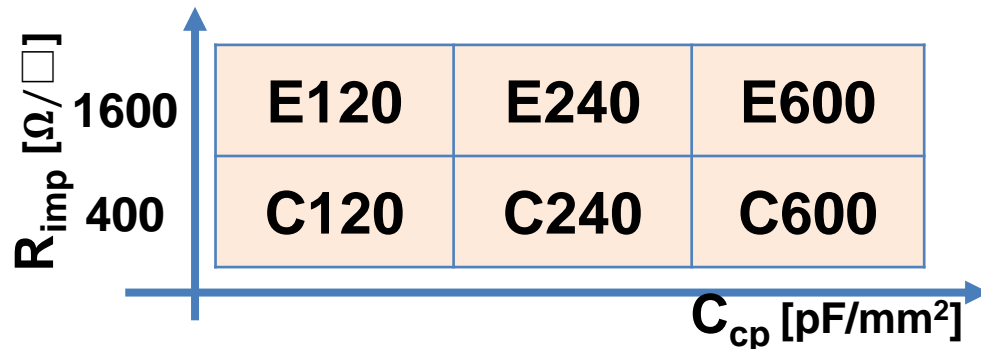
→ Electrode capacitance increased by factor of 5 !!

## Pixel sensor

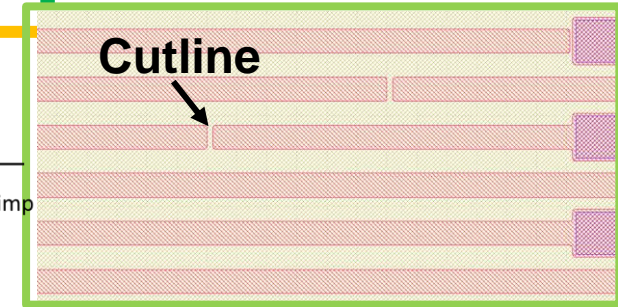
- Various of pitch



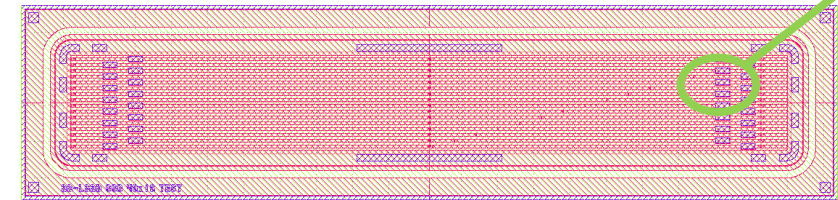
- 5 times larger  $C_{cp}$  compared with E-b (2020) type : E-600



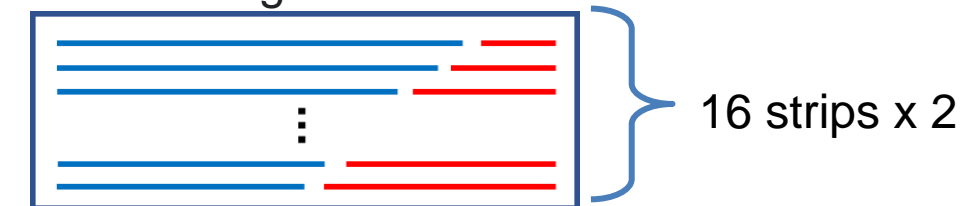
## Strip sensor



- Strip sensor which has different electrode length (to study inter electrode cap.)



Pattern diagram



AC-LGAD run II-b 17<sup>th</sup> November 2022

Received new wafers with the same design :

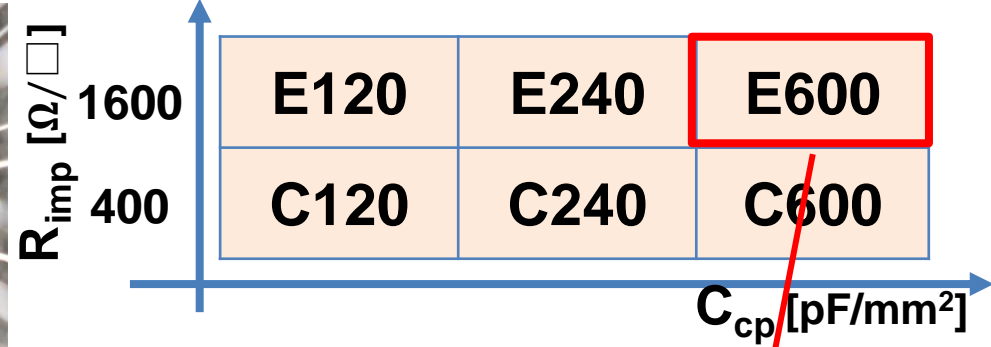
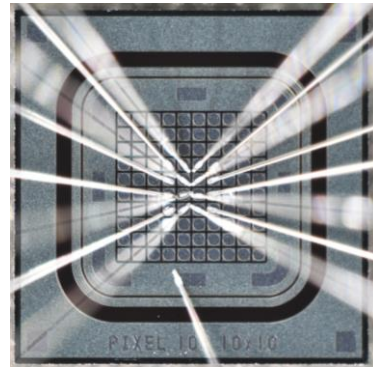
reduced active thickness 50um → 30/20um

Expecting better timing resolution (no results today)

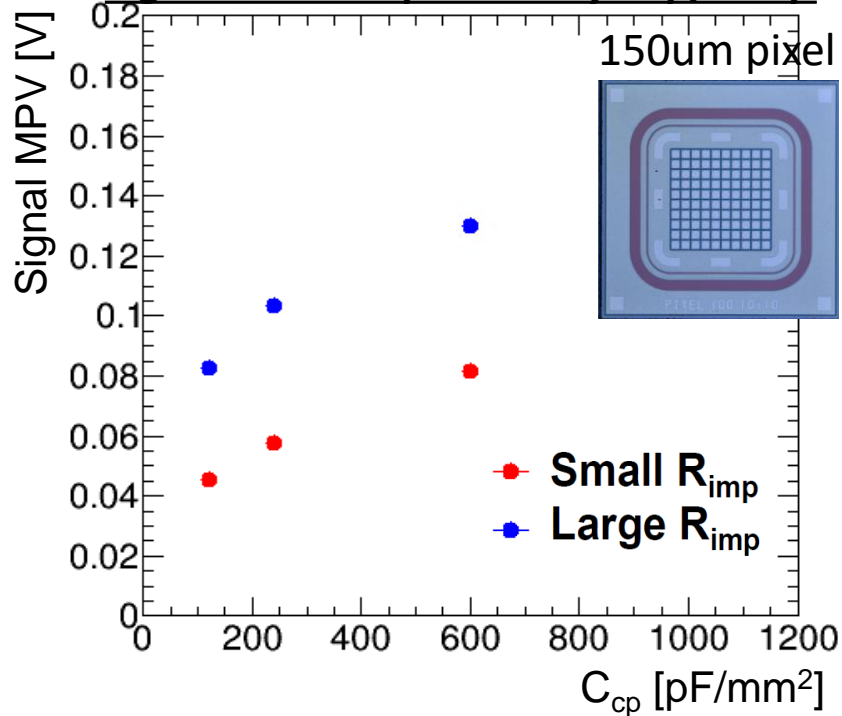


# Results for AC-LGAD pixel detector

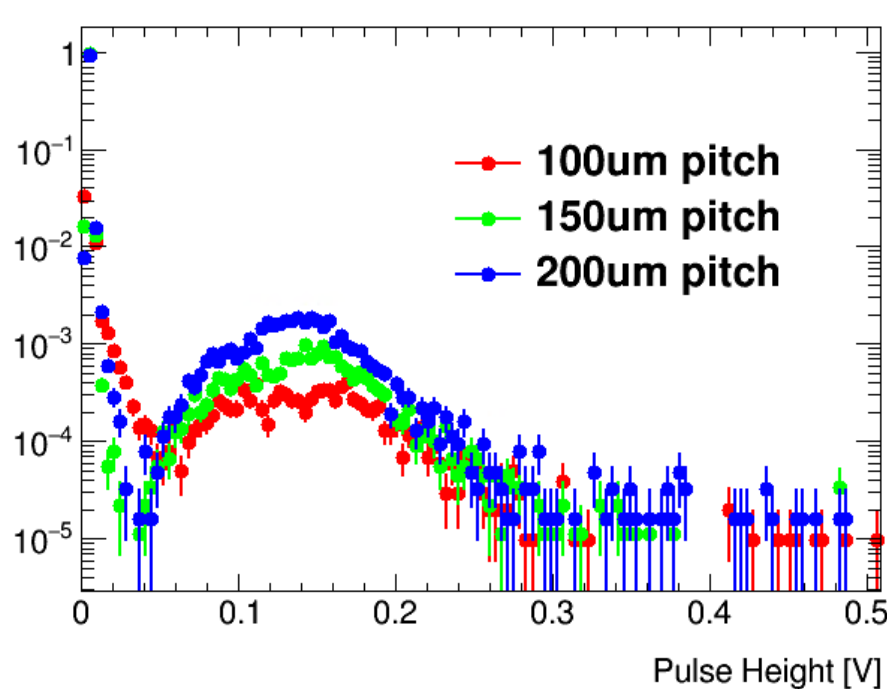
- Compared signal size of 6 types  $C_{cp}/R_{imp}$ .
  - 150um pixel sensors
  - Two n+ resistivity types and 3 Ccp types
- Compared signal size of 3 pixel size
  - 100/150/200um pitches are compared.



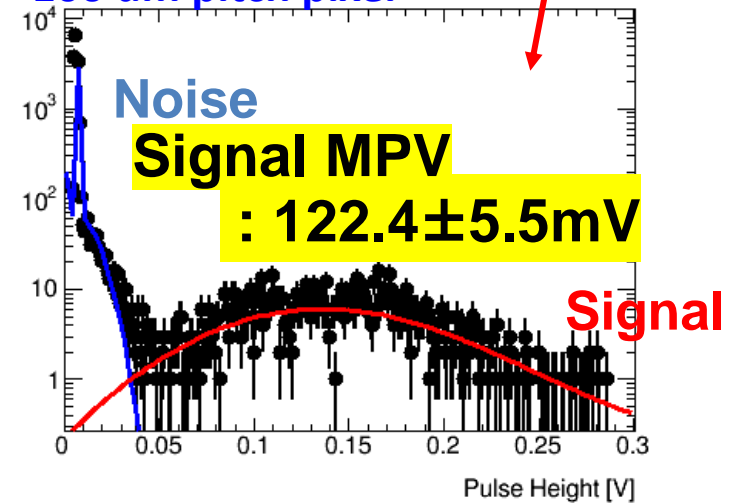
Signal size comparison by Ccp/Rimp



Pulse height comparison by pixel pitches



100 um pitch pixel

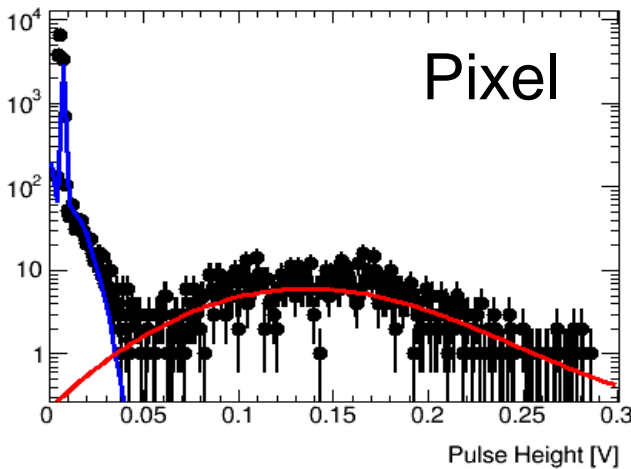
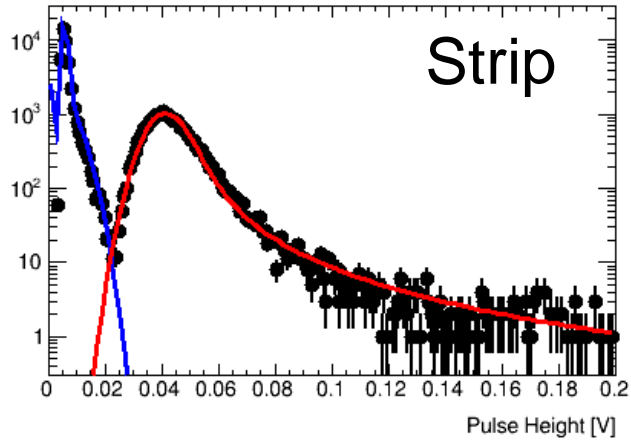


Successfully developed Good S/N 100um pitch pixel detector!

# Inter electrode capacitance effect ??

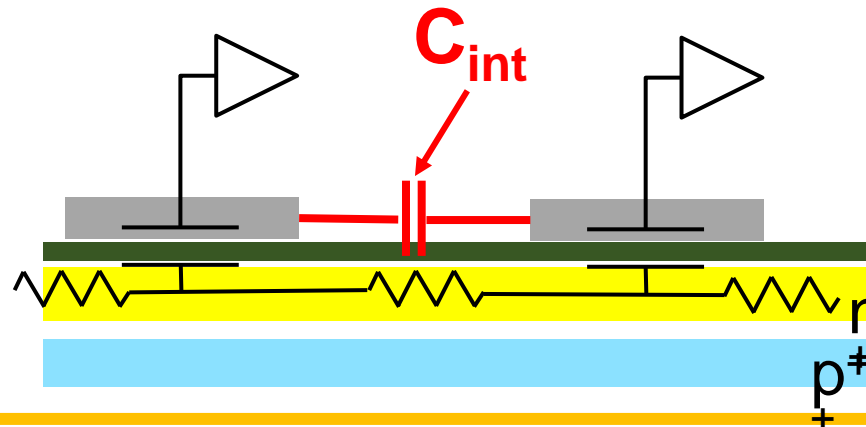
$$Q = \frac{Z_{R_{imp}}}{Z_{R_{imp}} + Z_{C_{cp}}} Q_0$$

Comparison of pulse height distribution between strip and pixel ...



	Strip	Pixel
Area of electrode	9880x45 $\mu\text{m}^2$	100x100 $\mu\text{m}^2$
$C_{cp}$ size of electrode	large	small
Signal size (expected from $C_{cp}$ )	large	small
Signal height (actual result)	$39.26 \pm 0.08 \text{mV}$ small	$122.4 \pm 5.5 \text{mV}$ large

## Inter electrode capacitance



## To check $C_{int}$ effect...

Compared signal size & cross talk  
For various length of strip electrodes

### Pattern diagram

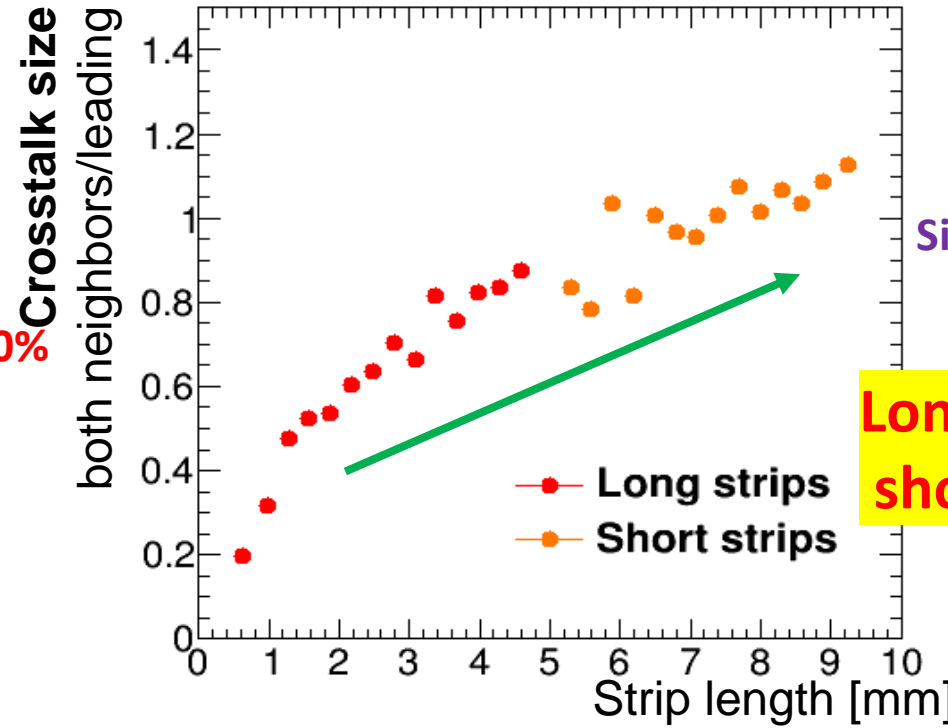
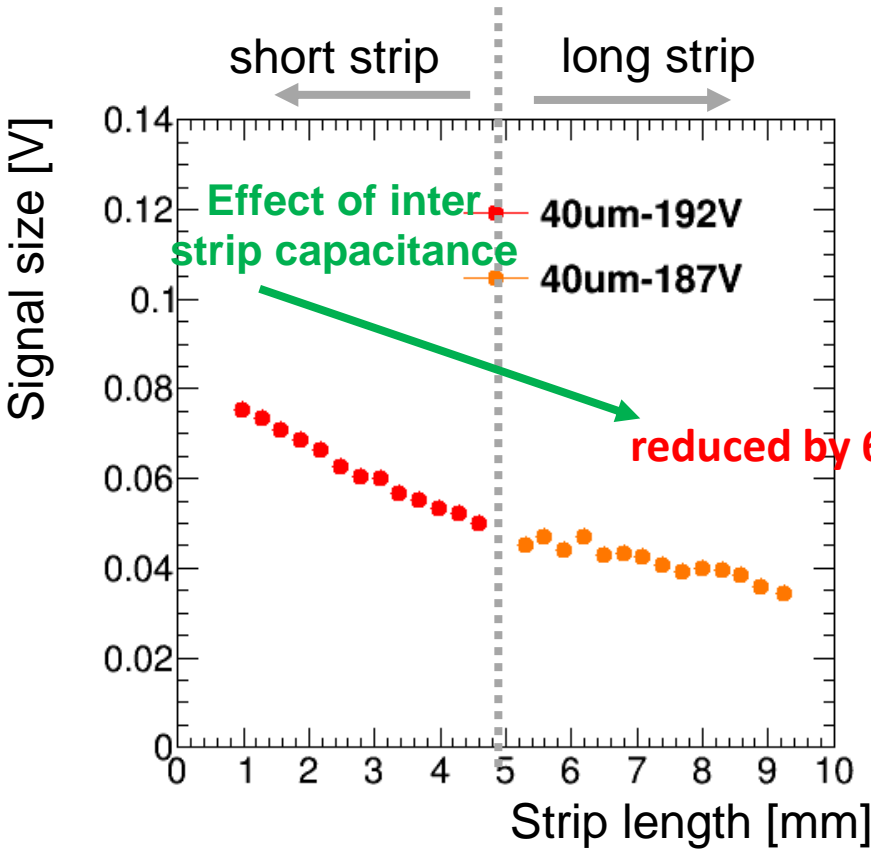
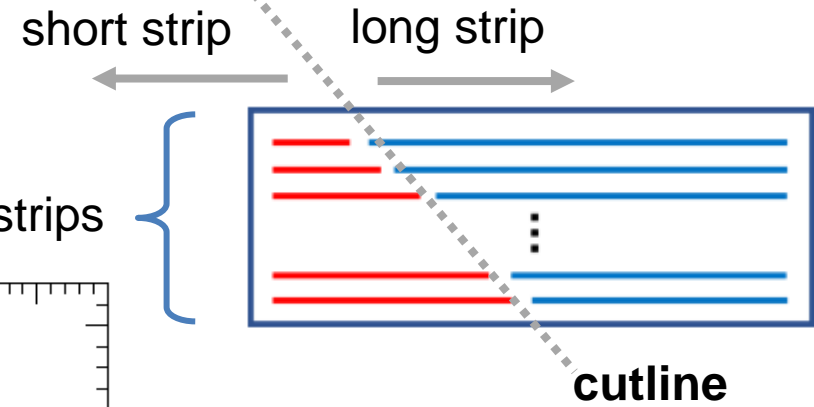


32 variation  
strip lengths

# Strip type electrode : inter strip capacitance

To evaluate the effect of signal attenuation and inter strip capacitance :

## E-600 type of strip sensor with cutline



Signal reduction is consistent to increase of crosstalk

**Longer strip detector should have worse S/N ratio**

Usual a few cm strip might not possible....

# Results & publication

Sayuka Kita *et. al.* VERTEX 2022 conference @ Tateyama Japan

## Conclusion

For inner tracker in hadron collider,  
**finer pitch AC-LGAD sensors** are prototyped with HPK.



Parameter optimization was performed.

Best type sensor (larger  $R_{imp}$  and  $C_{cp}$ ) : Larger signal height and smaller crosstalk !

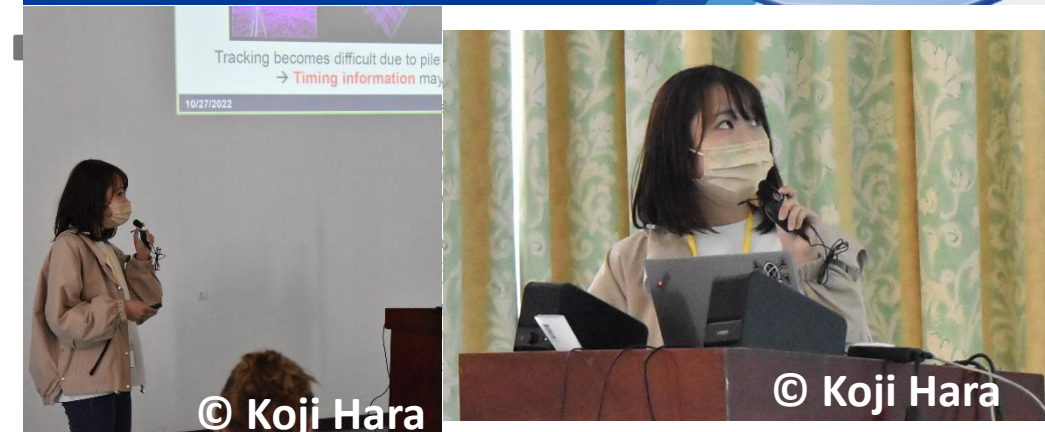
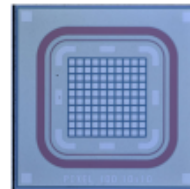
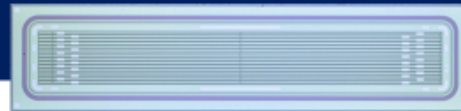
**successfully developed !!**

Pixel (100um pitch) → larger area prototype with ASIC

Strip (80um pitch)  $C_{int}$  makes strip signal smaller  
→ **Test longer strip sensor** to check if the crosstalk effect is saturated

### Todo

- Timing resolution
- radiation tolerance



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11/26/2022

Vertex2022

18

**Writing Proceedings for these results and will submit to JPS proceeding**

11:50 AM [F08] Development of AC-LGAD detector with finer pitch electrodes for high energy physics experiment 15m

Low-Gain Avalanche Diode (LGAD) sensor is one of candidate sensors for tracker at future hadron collider. To use this sensor as tracking detector, AC-LGAD sensor was developed which has both timing and spatial resolution. In high luminosity environment, a 30ps of timing resolution and  $O(10\mu\text{m})$  spatial resolution helps to reduce pileup effect and reconstruct tracks precisely. By optimization fabrication parameters, 80um pitch strip and 100um pitch pixel sensors are successfully produced. In this talk, I will present the performance of fine electrode pitch sensors such as pulse height, crosstalk size, timing resolution, inter electrode capacitance and radiation hardness evaluated using a beta-ray source and in 800MeV electron testbeam.

Speaker: Sayuka Kita (University of Tsukuba(JP))

Vertex2022\_kita.pdf

# What's next? : 3 key development

Timing resolution of pixel and strip detector

Improvement

measurement

MCP-PMT

Infra Red Laser

Radiation tolerance

Improvement

Large size prototype  
Gain Uniformity

EIC prototype

HGTD prototype

*Fermilab testbeam*

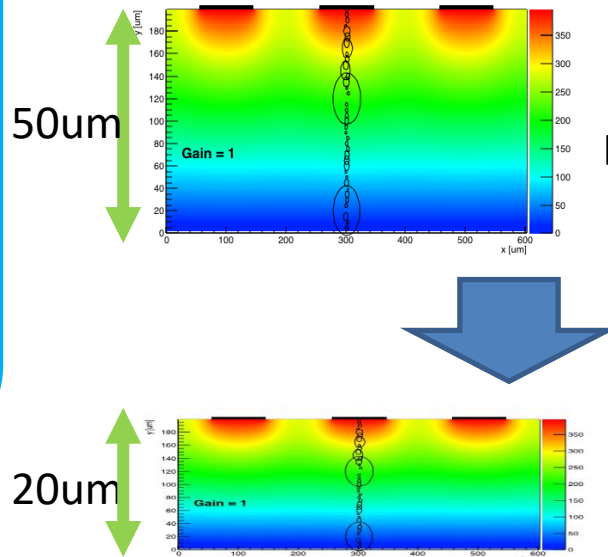
New Application to  
Collider detector

# What's next? : 3 key development

## Timing resolution of pixel and strip detector

### Improvement

### Non-Uniform charge deposition



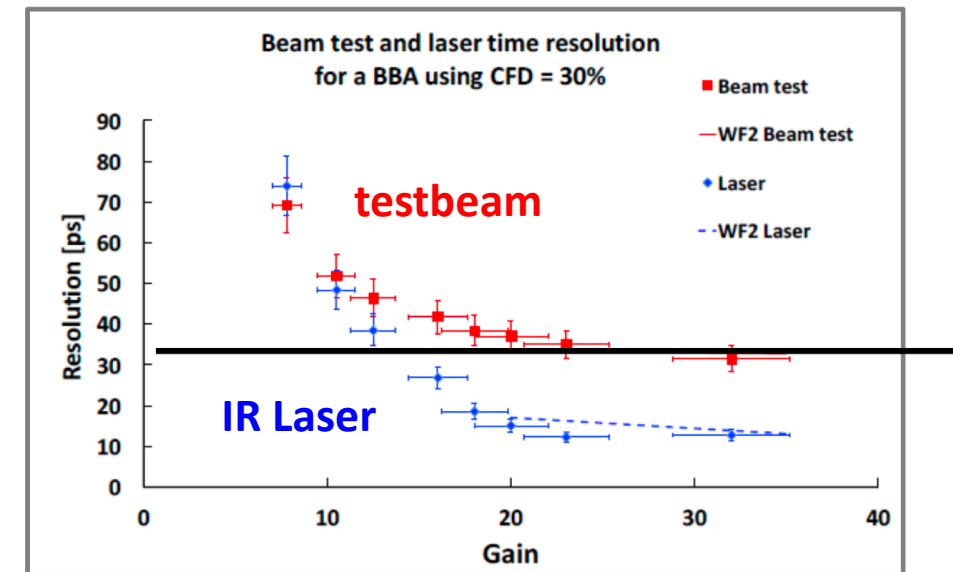
$$I_{ind} = \sum_i q_i \vec{v}_{drift,i} \cdot \vec{E}_{w,i}$$

Introduces landau fluctuation of induced charge

**Thinner active thickness  
will help to reduce the effect**

30um and 20um active thick sensor have been received this month.

→ Results will come soon

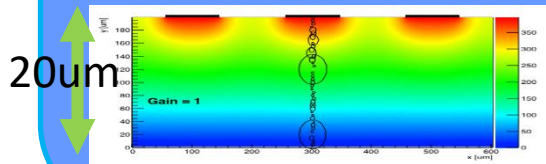


# What's next? : 3 key developments

## Timing resolution of pixel and strip detector

### Improvement

New prototype wafer to reduce Landau noise



### measurement

MCP-PMT

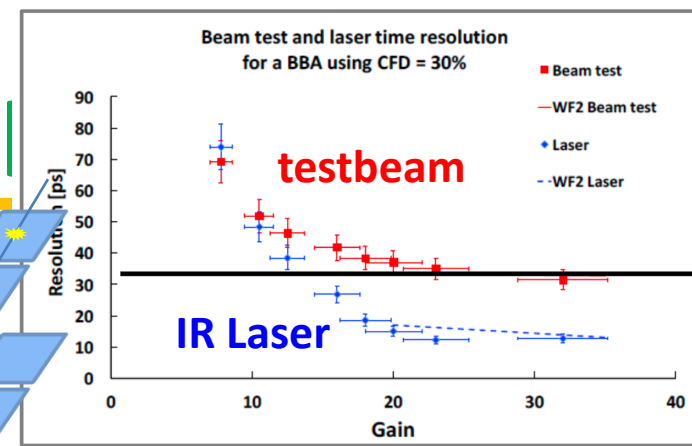
Infra Red Laser

Previously...

2 layer coincidence

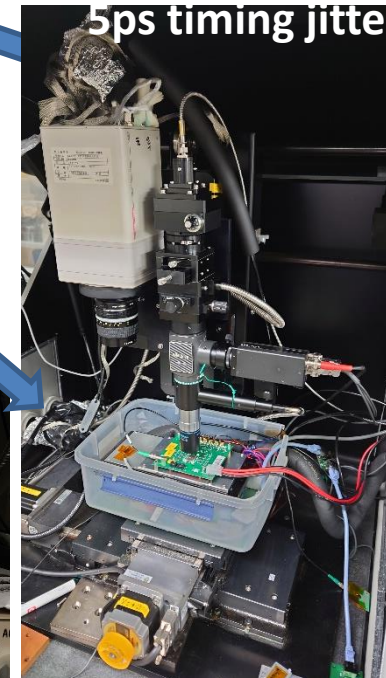
$$\rightarrow \sigma_t = \sigma_{\Delta t} / \sqrt{2}$$

Takes very long time to take data for small electrode



RI laser (pico second)

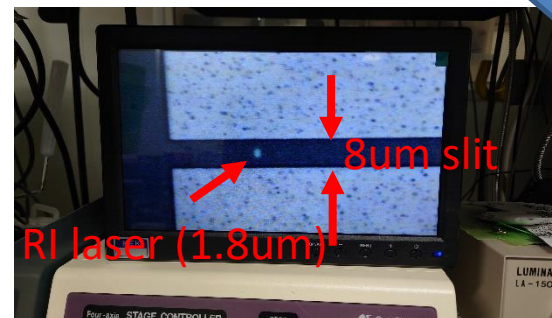
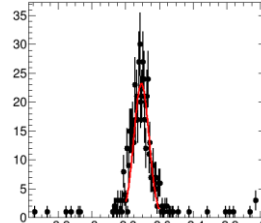
5ps timing jitter



Photek PMT 240

~8ps timing resolution

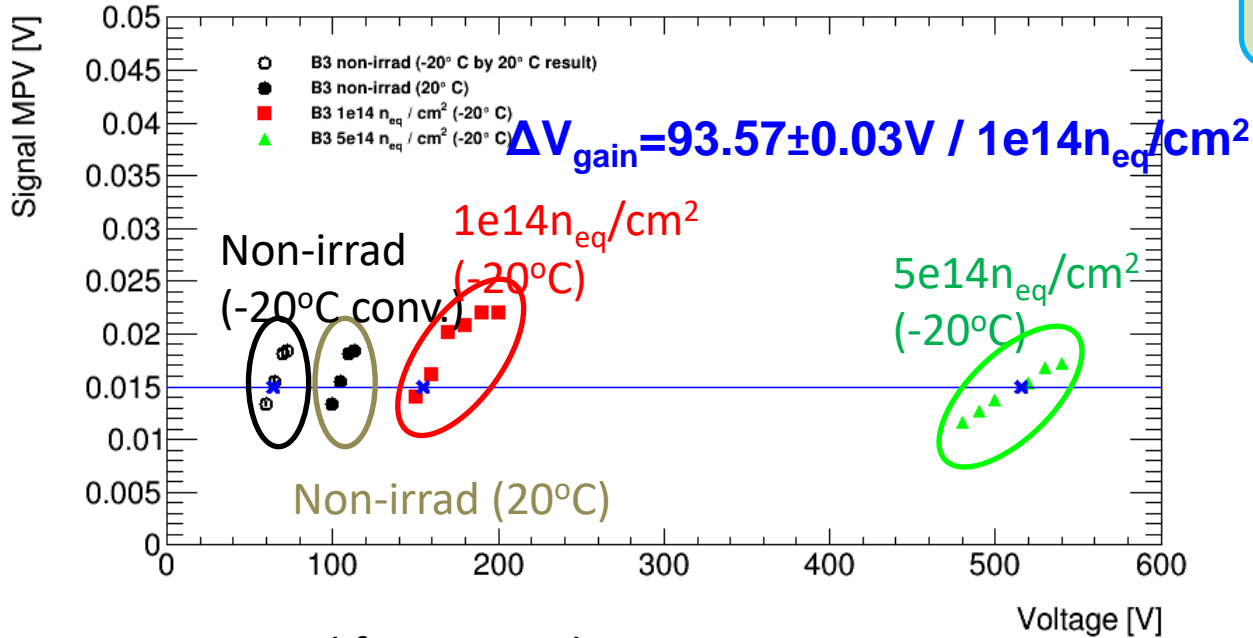
$\sigma = 44.7 \pm 2.1$  ps



# What's next? : 3 key development

Radiation tolerance for the current sensor is not optimal.

→ Survive only upto  $<1e15 n_{eq}/cm^2$



**Radiation tolerance**

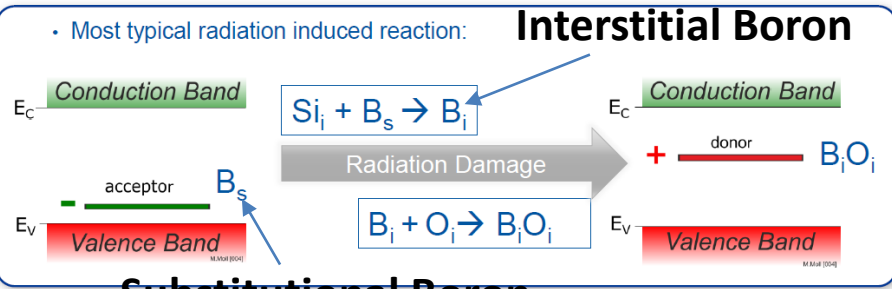
*Large size prototype*  
*Gain Uniformity*

**Improvement**

**EIC prototype**

**HGTD prototype**

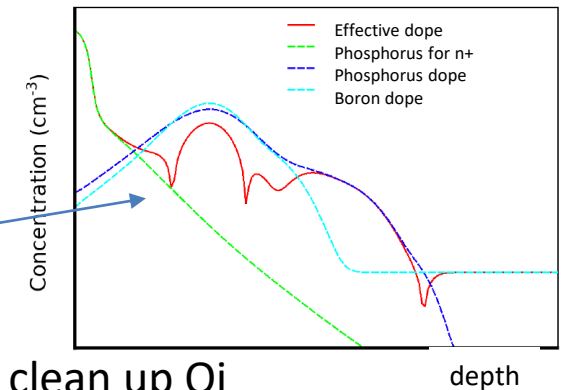
Acceptor removal for p+ gain layer



**Substitutional Boron**

Waiting New Samples

1. Carbon annealing
  - $B_i + C_s \rightarrow B_iC_s^* \rightarrow B_s + C_i$
2. Compensation method
  - Add Boron + Phosphorus
3. In-active Boron?
  - 10 times Bi at the beginning to clean up Oi





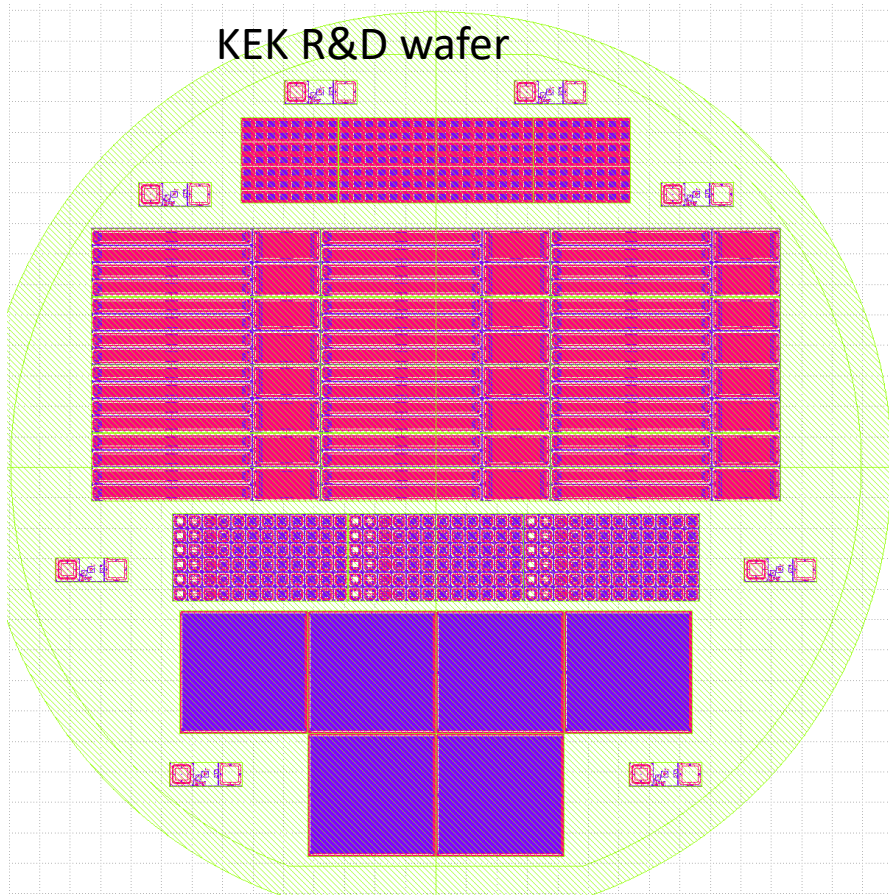
# What's next? : 3 key development

## JFY 2022 sample

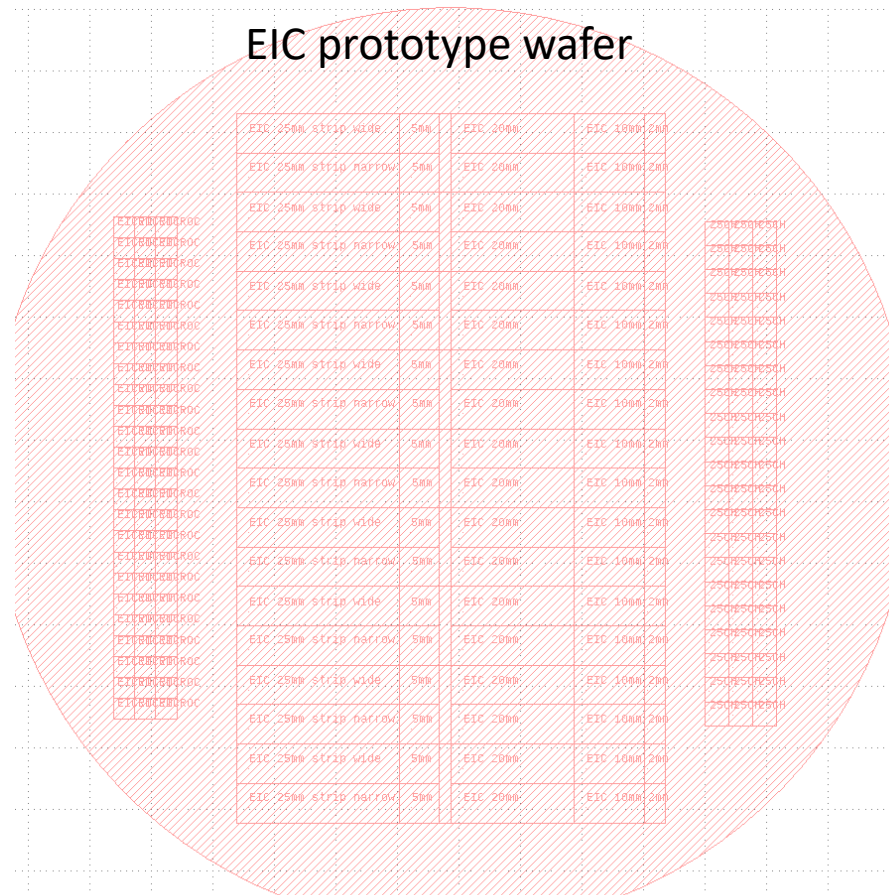
Implemented 20mm x 20mm pixel sensor (compatible to ATLAS ITk chip)

KEK R&D : smaller electrodes, EIC prototype : all 500um pitch strip and pad

KEK R&D wafer



EIC prototype wafer



**Large size prototype**  
**Gain Uniformity**

**EIC prototype**

**HGTD prototype**



**New Application to  
Collider detector**

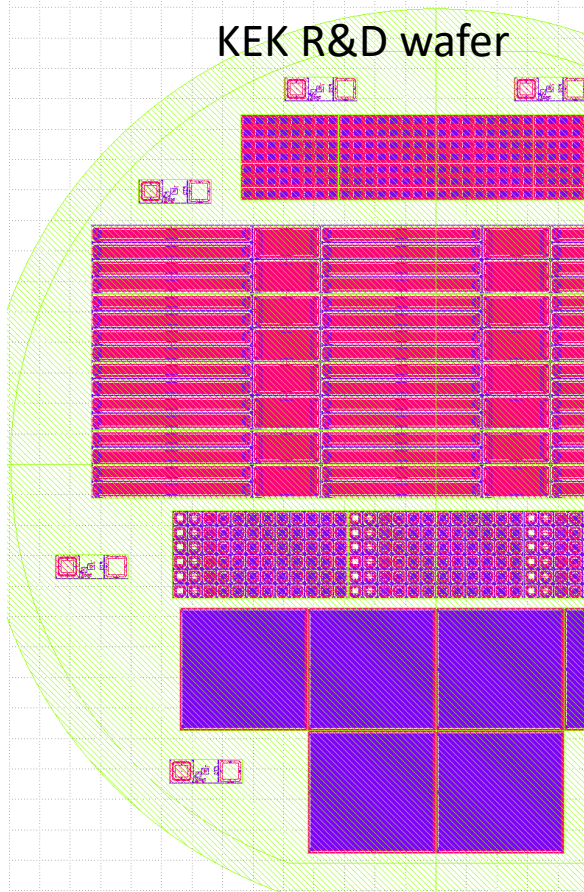
Could be a candidate of ATLAS HGTD replacement?

# What's next? : 3 key development

## JFY 2022 sample

Implemented 20mm x 20mm  
KEK R&D : smaller electro

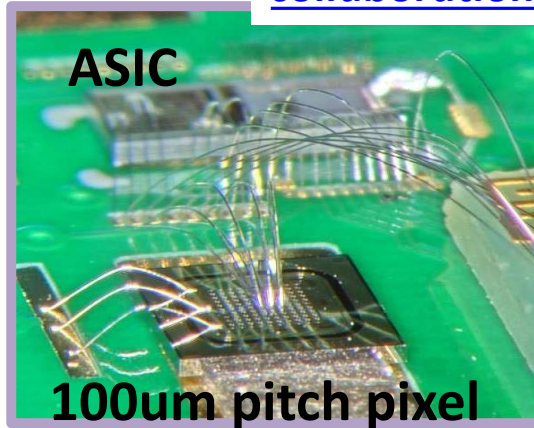
KEK R&D wafer



Could be a candidate of ATLAS HEPD replacement.

**Certainly... need fast and multi-channel readout ASIC**

Fulvio Martinelli et. al. Si-Ge Bi-CMOS ASIC  
collaboration with University of Geneva



10x10 channels (100um pitch)  
with 3 analog + 1 discri. output



**Small size prototype**  
**in Uniformity**

**C prototype**

**TD prototype**



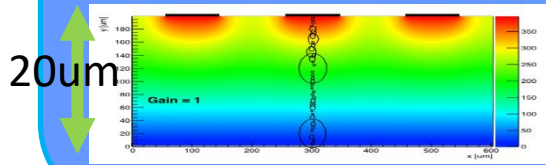
**Application to  
Collider detector**

# What's next? : 3 key development

## Timing resolution of pixel and strip detector

### Improvement

New prototype wafer to reduce Landau noise



### measurement

**MCP-PMT**  
8ps timing resolution

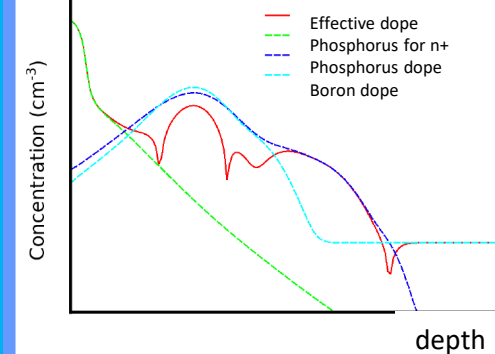


**Infra Red Laser**  
5ps timing jitter  
1.8um focus size



## Radiation tolerance

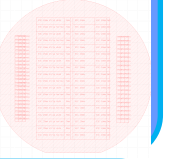
### Improvement



## Large size prototype Gain Uniformity

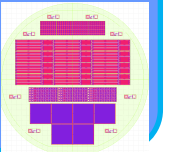
### EIC prototype

3cm length  
500um pitch strip



### HGTD prototype

2cm x 2cm  
100um pitch pixel



**Fermilab testbeam : Feb-March 2023 @ FTBF**

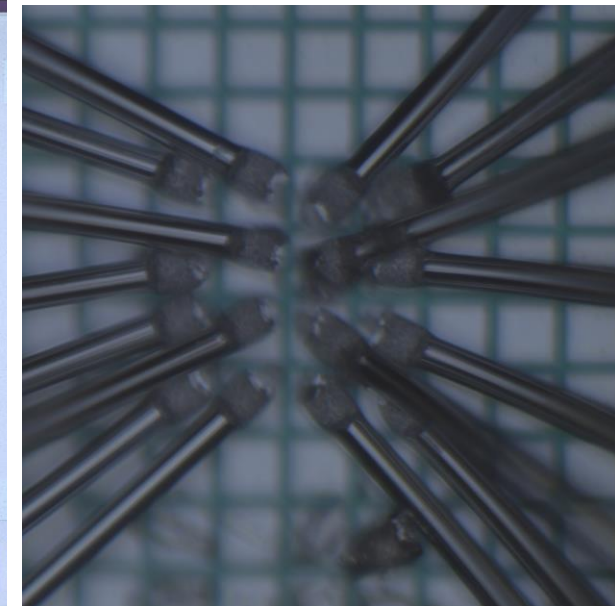
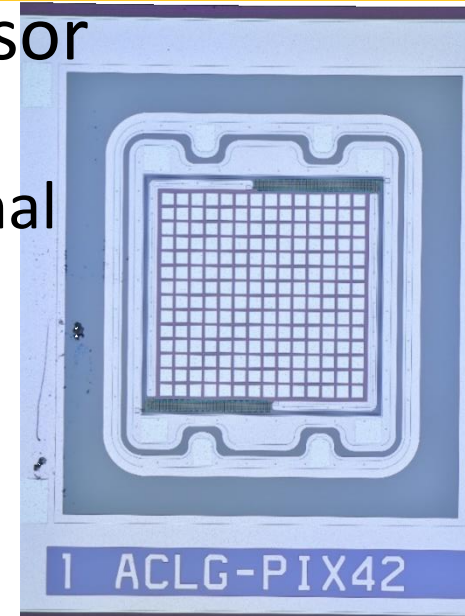
**New Application to Collider detector**

# backup

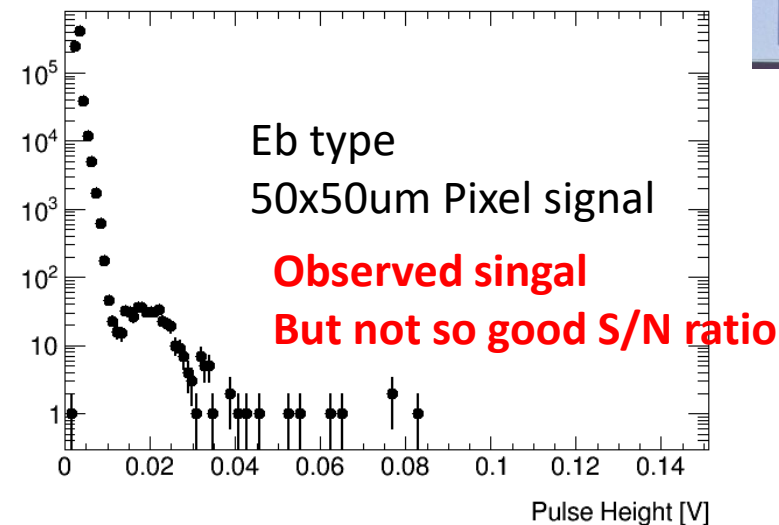
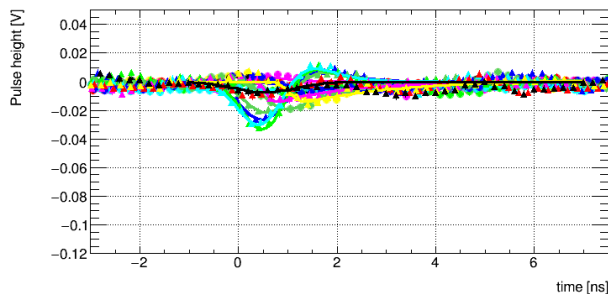
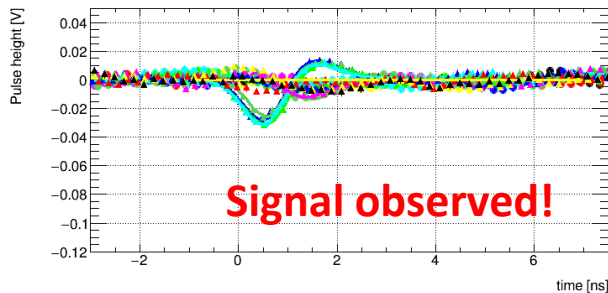
---

# Challenge : Pixel detector

- Prototype of 50um x 50um pitch pixel sensor
  - Wirebonded only 4x4 array at the center.
  - First observation of AC-LGAD pixel sensor signal
    - Smaller signal and larger cross talk observed
    - **S/N ratio is not enough and need improvement.**



Pulse height distribution



**Clearly need improvement**

Coupling capacitor  $C_{cp}$  (Effective area?)

pad 500um	strip 45um	pixel 50um
500um	9880um	50um
$n^+$	$n^+$	$n^+$
MPV : 100mV	38mV	<15mV

**Need high  $C_{cp}$  sensors → JFY2021 sample to be tested**

# What should be understood and what's next?

- Understand Strip detector

- Why so small signal?

- How much effect of interstrip capacitance?

- Significantly smaller signal compared with pad type detector.

- How much signal attenuation in the strip?

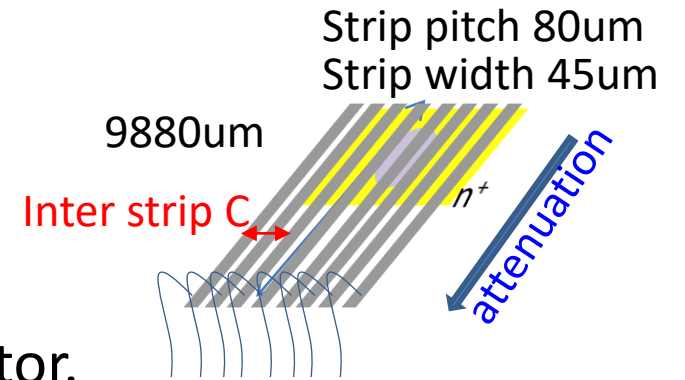
- This might affect to the signal size un-uniformity and delay of signal readout.

- Certainly we want to develop pixel type detector.

- First 50um x 50um pixel sensor does not have enough signal size.

- What is the minimum pixel size we can see good S/N signal?

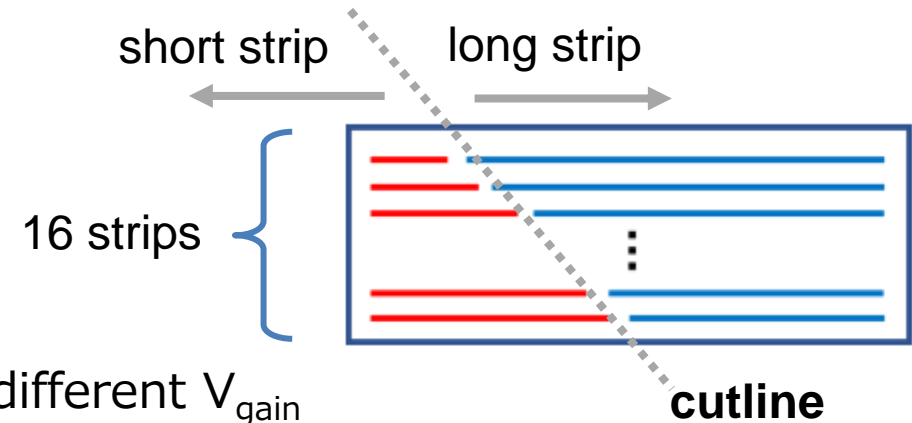
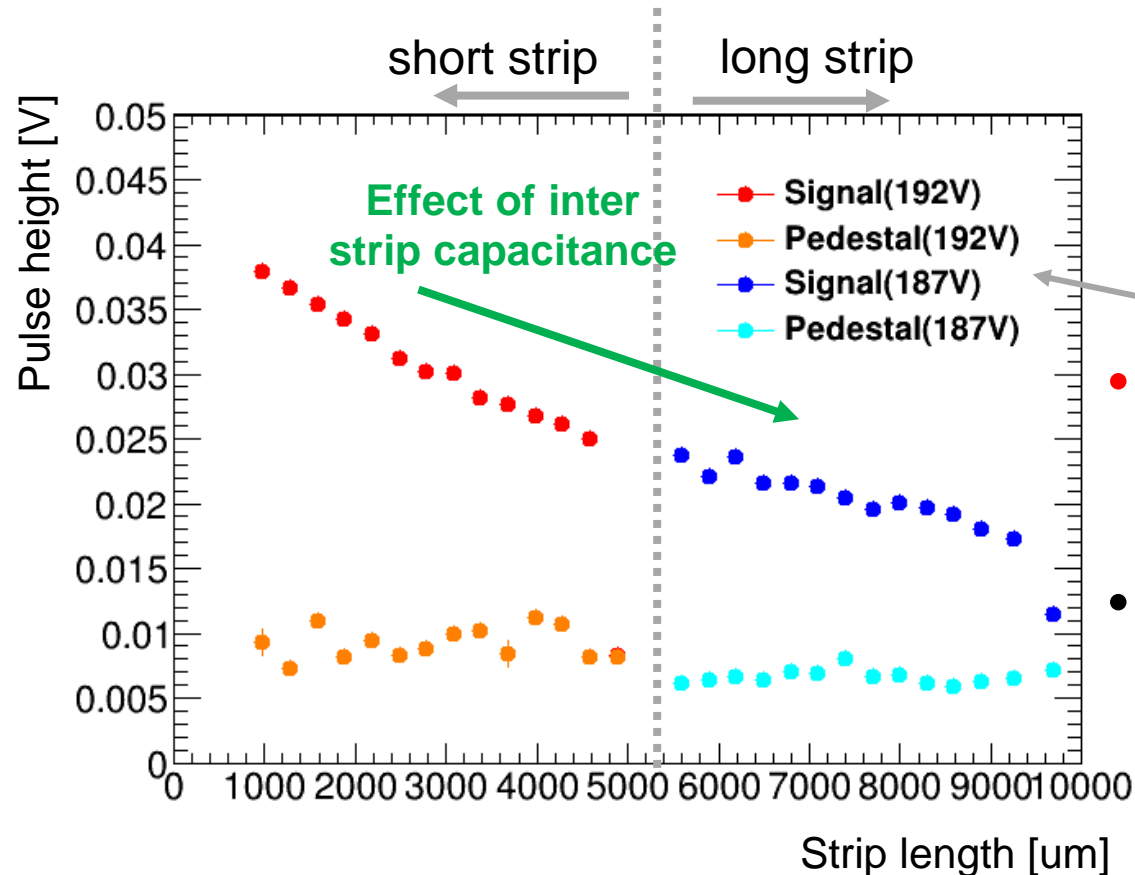
- What is the effective area for electrode capacitance ?



# Preliminary results : Strip type electrode

To evaluate the effect of signal attenuation and inter strip capacitance :

## E-600 type of strip sensor with cutline



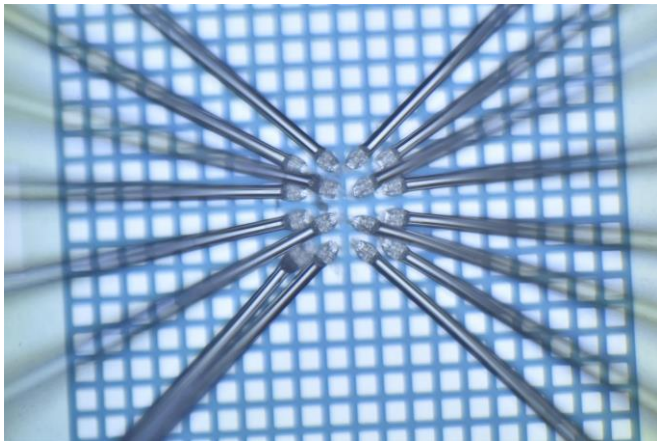
- Due to different  $V_{gain}$
- **Signal reduced by 60% in ~10mm**
  - Because of inter strip capacitance?
  - Because of signal attenuation?
- We will test smaller gap sample. (the same pitch)
  - Current gap 40um  $\rightarrow$  20um
  - **Smaller gap have larger inter strip capacitance and smaller attenuation**

# Preliminary results : Pixel type electrode

What is the minimum pixel size we can see good S/N signal?

## E-600 type of pixel sensor

4x4 pixels are wirebonded.



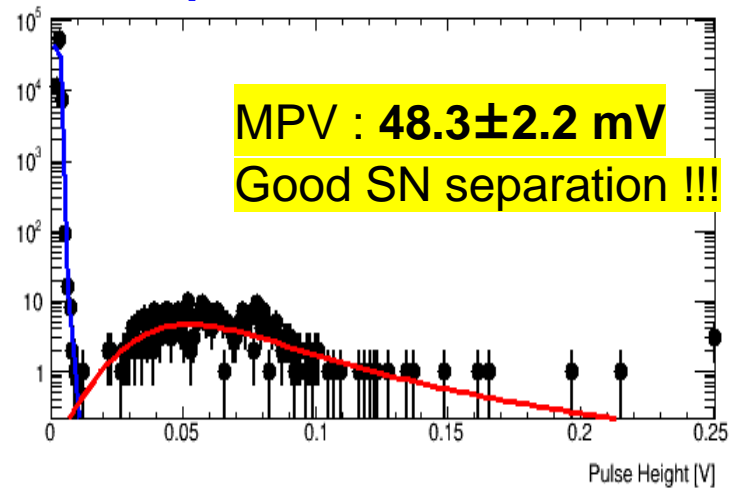
	7	11	
	6	10	

### Analysis

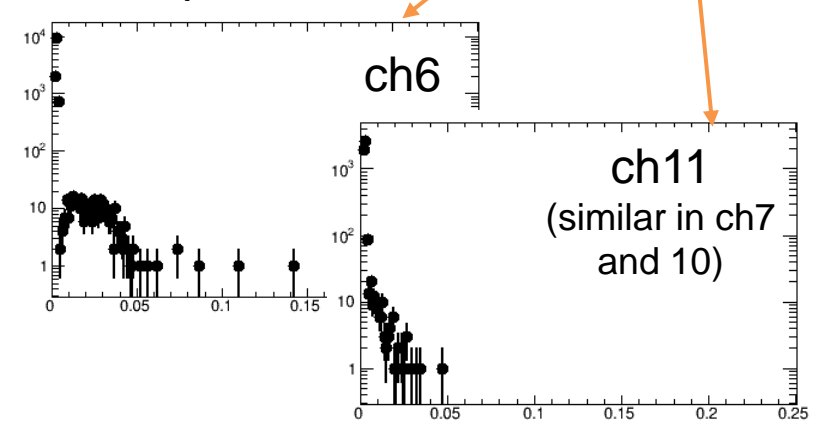
Only center 2x2 channels was used.  
(To avoid crosstalk effect)

Pulse height distribution

100um pitch



50um pitch



Electrode short in ch6 ?  
under investigation ...

**First Pixelated AC-LGAD in the World! (100um x 100um)**

We need to understand the 50um x 50um pixel

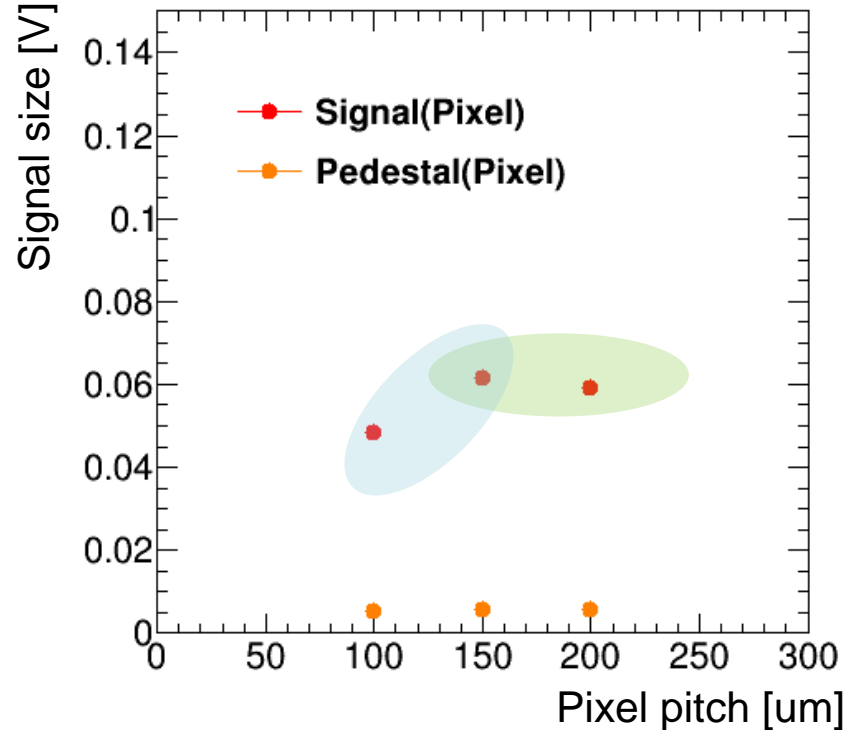


# Preliminary results : Pixel type electrode

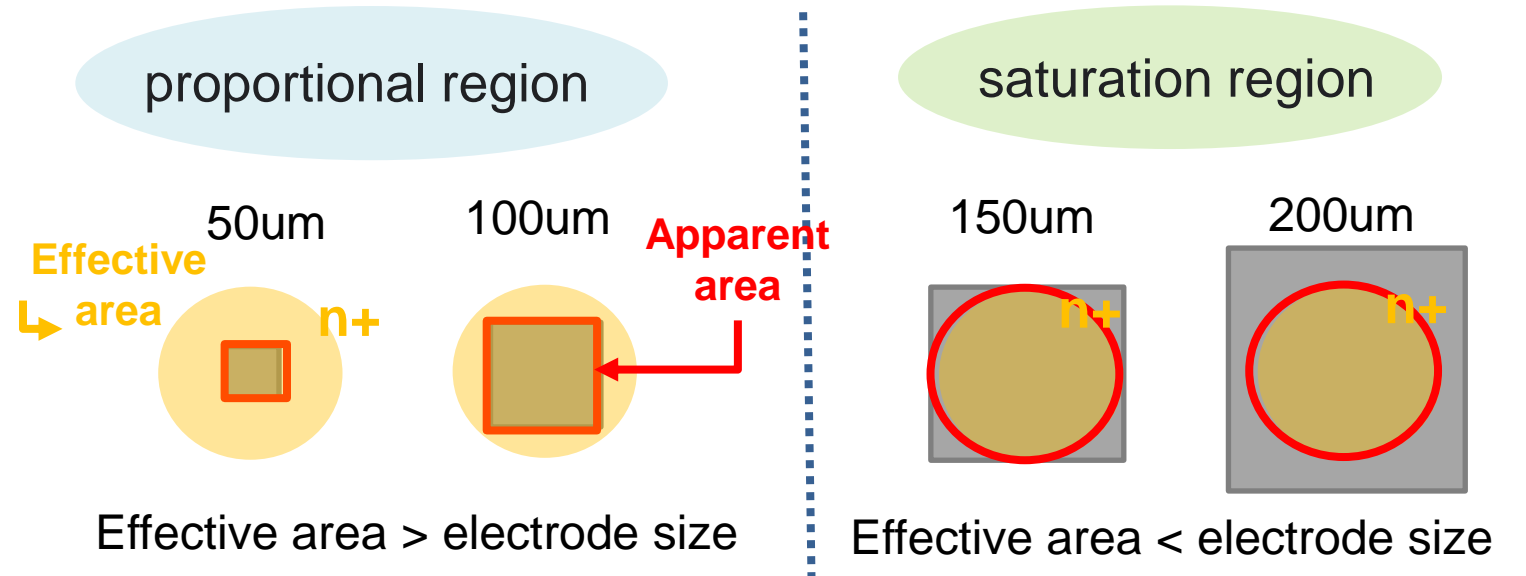
## What is the effective area for electrode capacitance ?

### E-600 type of pixel sensor

(all supplied 190V)



Tested various size of pixel sensor to see the saturation of signal size

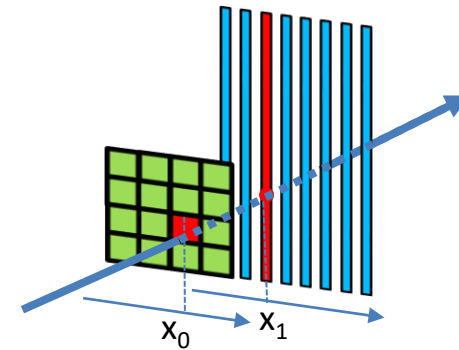


- **Signal seems like saturated at ~150um**
  - It makes sense small signal of 50um x 50um sample
  - **Will test smaller n+ resistivity sample**
    - Expected larger effective area.

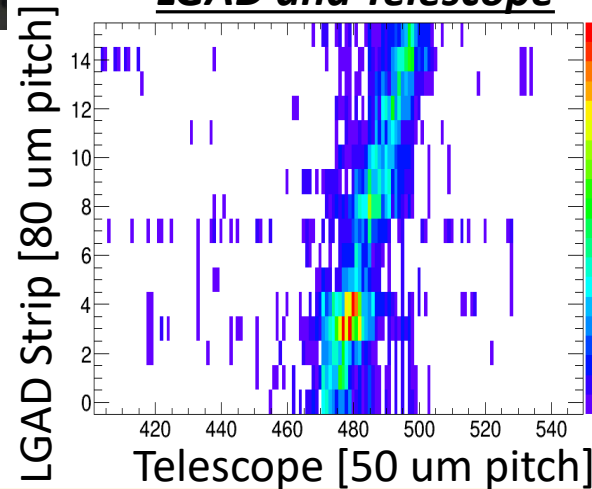
# Snap shot from on-going ELPH testbeam

- ELPH testbeam (6/17-24)
    - 800MeV electron beam
  - Took huge set of data
    - Pad/Strip/Pixel sensors
    - Combined run with 100um pixel and 80um strip sensor
- First LGAD tracker!!

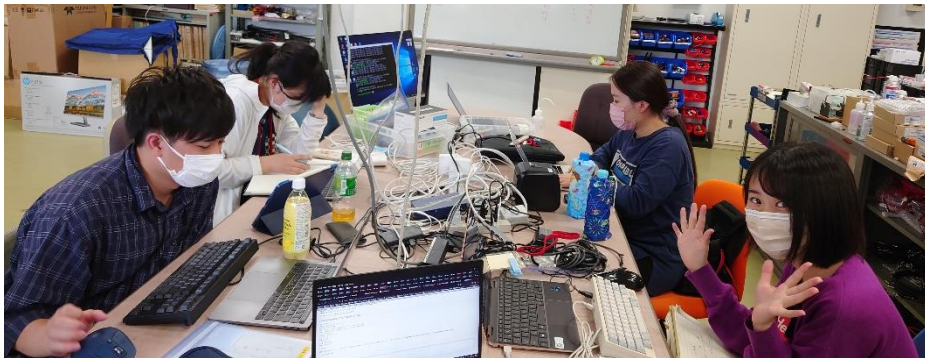
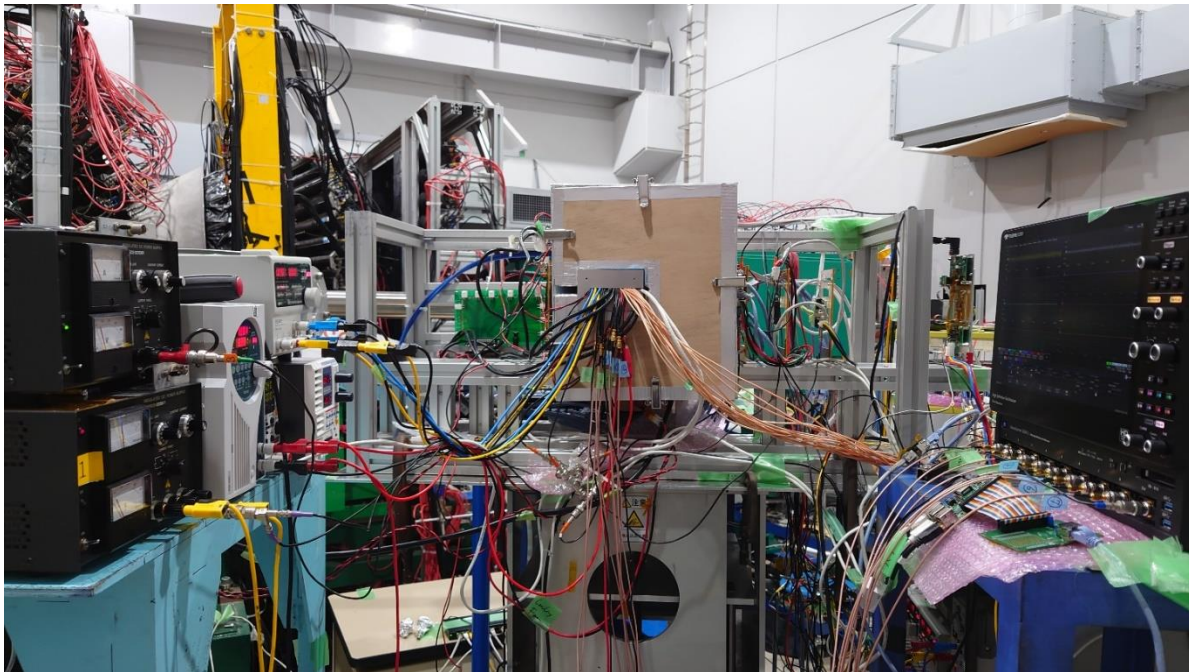
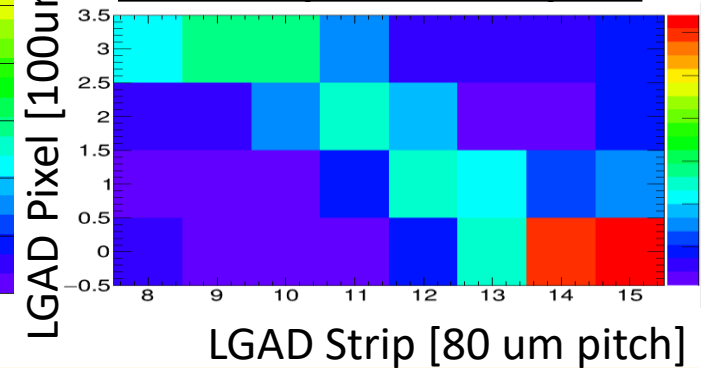
Correlation of x position of two planes



LGAD and Telescope



LGAD Strip and LGAD pixel

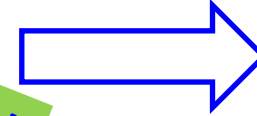


# Conclusion

2019,20 sample

**ACLGAD with 80um pitch strip sensor**  
Good S/N ratio : 99.98% at 1e-4 noise rate

First high spatial resolution LGAD!

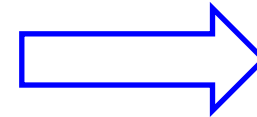


Small signal due to :  
inter strip capacitance?  
attenuation in strip?  
→ Strip specific issue

2021 sample

**ACLGAD with 100um x 100um pixel sensor**  
Larger signal than strip sensor!!

First pixelated LGAD!



Much better solution !

Home work 1

**LGAD detector with 50um x 50um**  
Challenging but need to find a way

Home work 2

**LGAD detector with Radiation tolerance**  
Currently up to  $1.0 \times 10^{15} n_{eq}/cm^2$

# backup

---

# Next generation of Collider experiment

## Need "Higher Luminosity" and/or "Higher Energy"

### – High Luminosity LHC (HL-LHC)

- 20 times more data ( $\sim 3000-4000\text{fb}^{-1}$ ) at **14TeV**
- Plan : Start at 2029

### – High Energy LHC (HE-LHC)

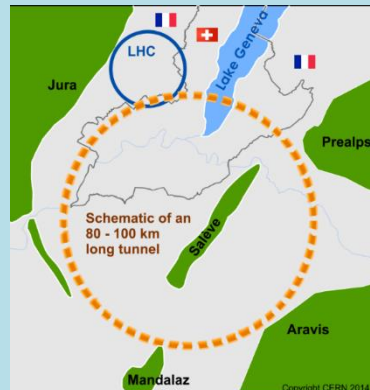
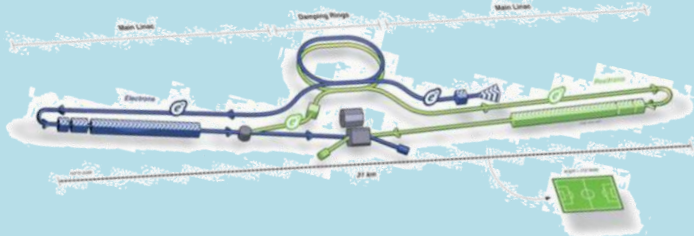
- Use Super Conducting Magnet with Higher Magnetic field(16T)
- **28TeV** collider in the same tunnel as LHC.

### – Future Circular Collider (FCC-hh)

- Use Super Conducting Magnet with Higher Magnetic field(16T)
- **100TeV** collider with 100km tunnel at CERN.

### – International Linear Collider (ILC)

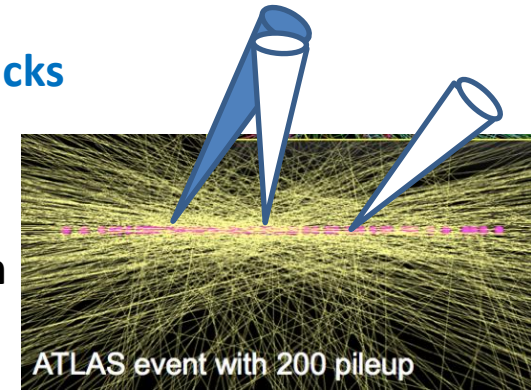
- 250GeV  $e^+ e^-$  collider in Japan



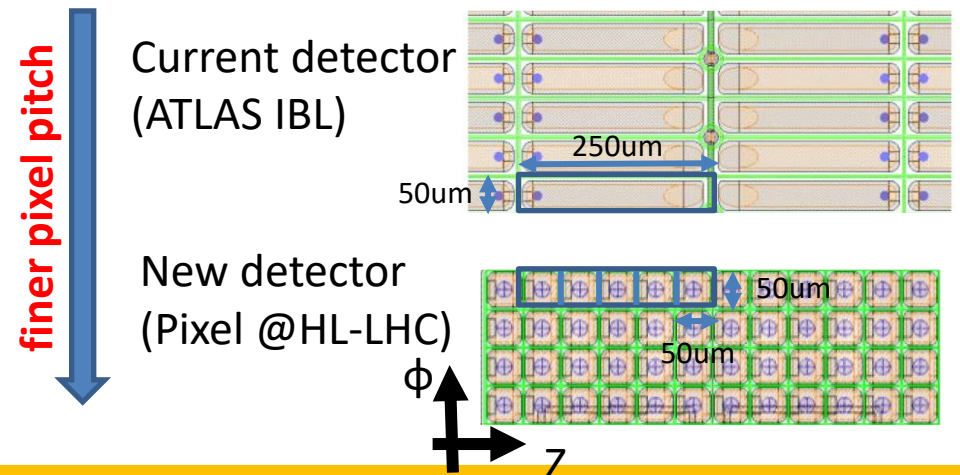
## Inner Tracking system

Very high density tracks

140 pileup @ HL-LHC  
1500 pileup @ FCC-hh



Only way to solve this so far...



Coming soon

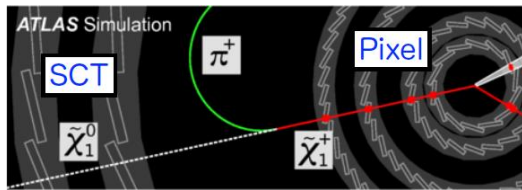
Discussion Started

Discussion Started

Final decision soon

# Physics impact of timing detector

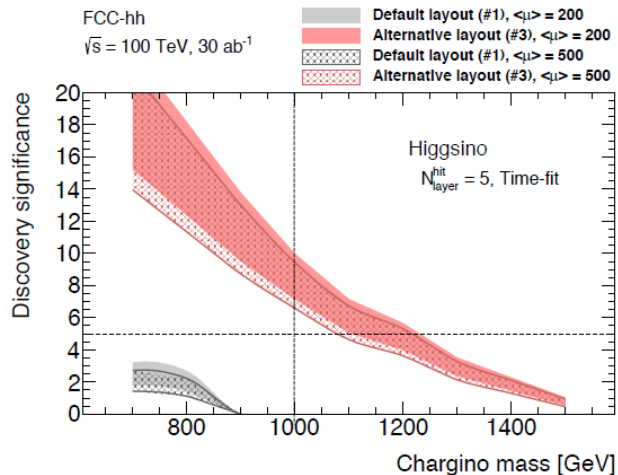
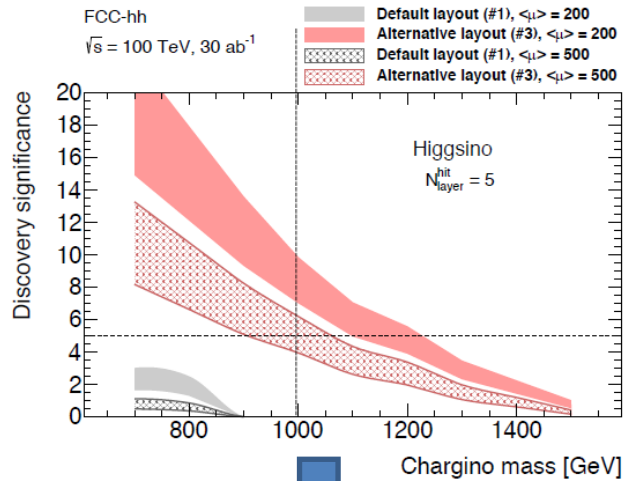
## Higgsino production by using disappearing track



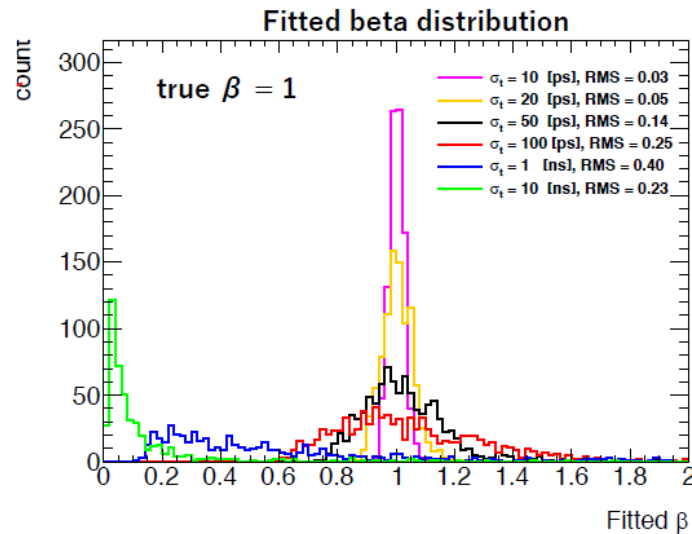
LSP: higgsino  
 $\Delta m(\tilde{\chi}^{\pm}, \tilde{\chi}^0) \sim 300 \text{ MeV}$   
 $\tau_{\tilde{\chi}^{\pm}} \sim 0.04 \text{ ns}$  ( $c\tau \sim 12 \text{ mm}$ )

Used timing information  
 only for pileup removal

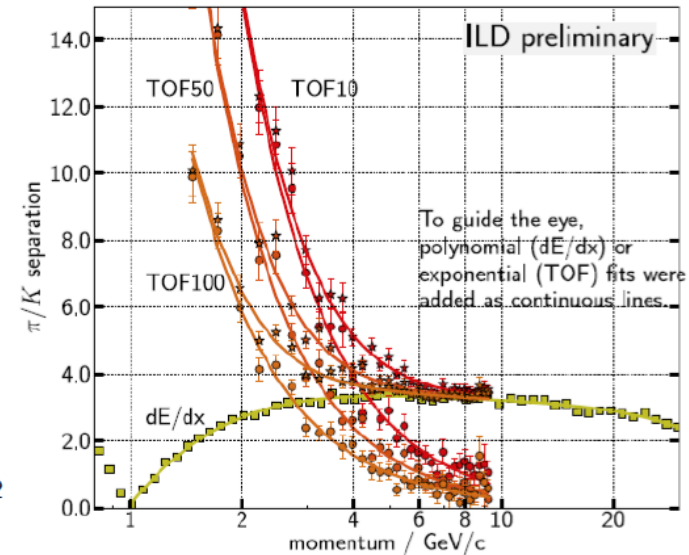
50ps timing  
 information



## $\beta$ measurement in FCC detector



## ILC K/pi separation



- See more information in timing detector workshop in 2018:

<https://indico.cern.ch/event/747424/timetable/#20181208>

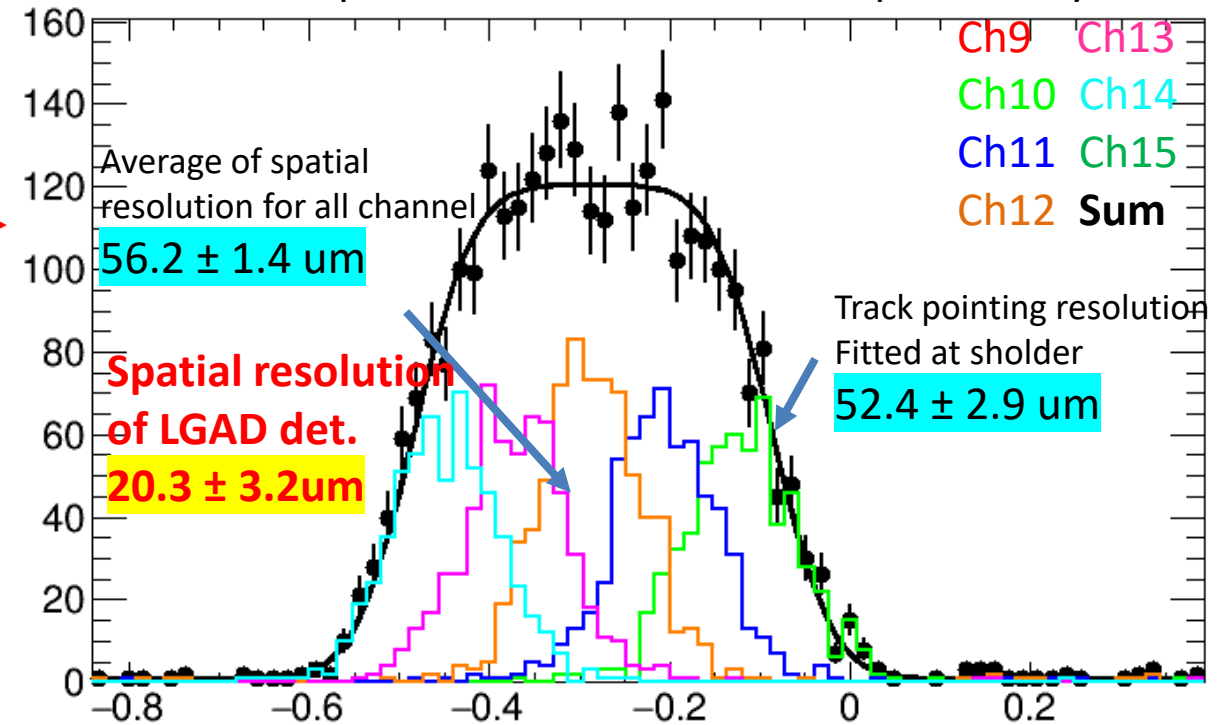
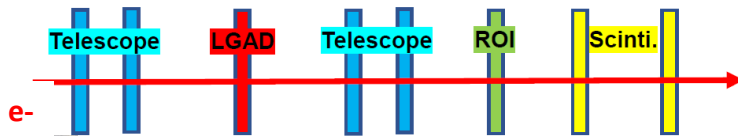
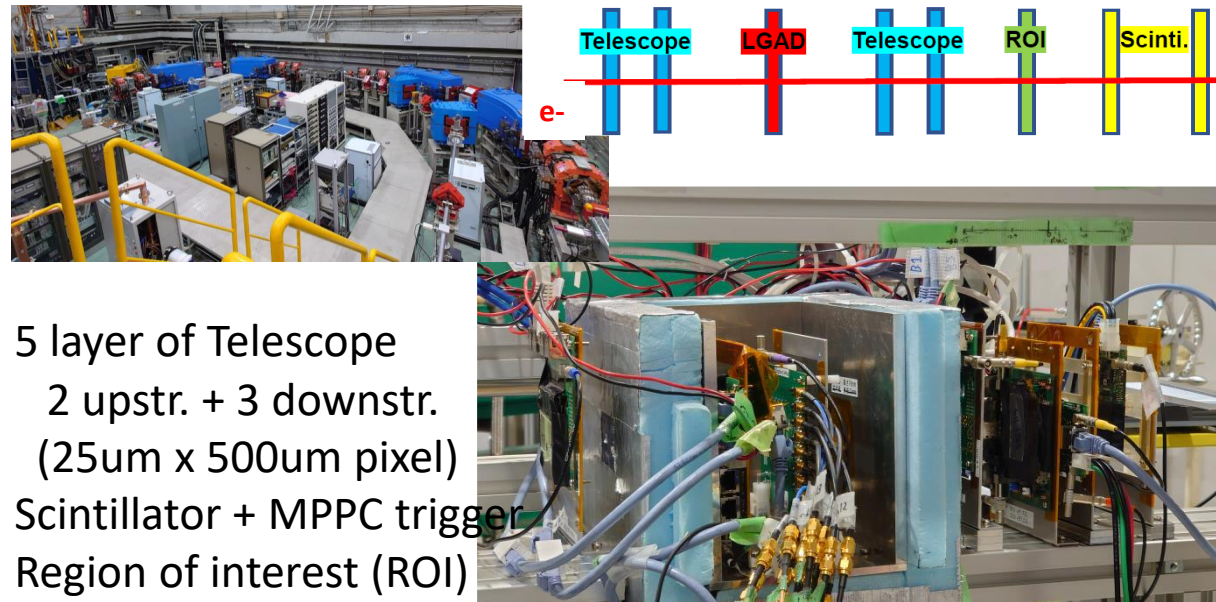
# Spatial resolution measurement at ELPH TB



- In principle, no dead area and small crosstalk
  - At least  $23\mu\text{m}(80\mu\text{m}/\sqrt{12})$  resolution by binary readout
- ELPH testbeam at Tohoku Univ. (8-9 July 2021)
  - 800MeV electron beam
  - Trigger rate 200-400Hz
  - Strip E-b type 170V @ 20°C

Huge Multiple-Scattering

Residual distribution of hit position and reconstructed position by tracking.



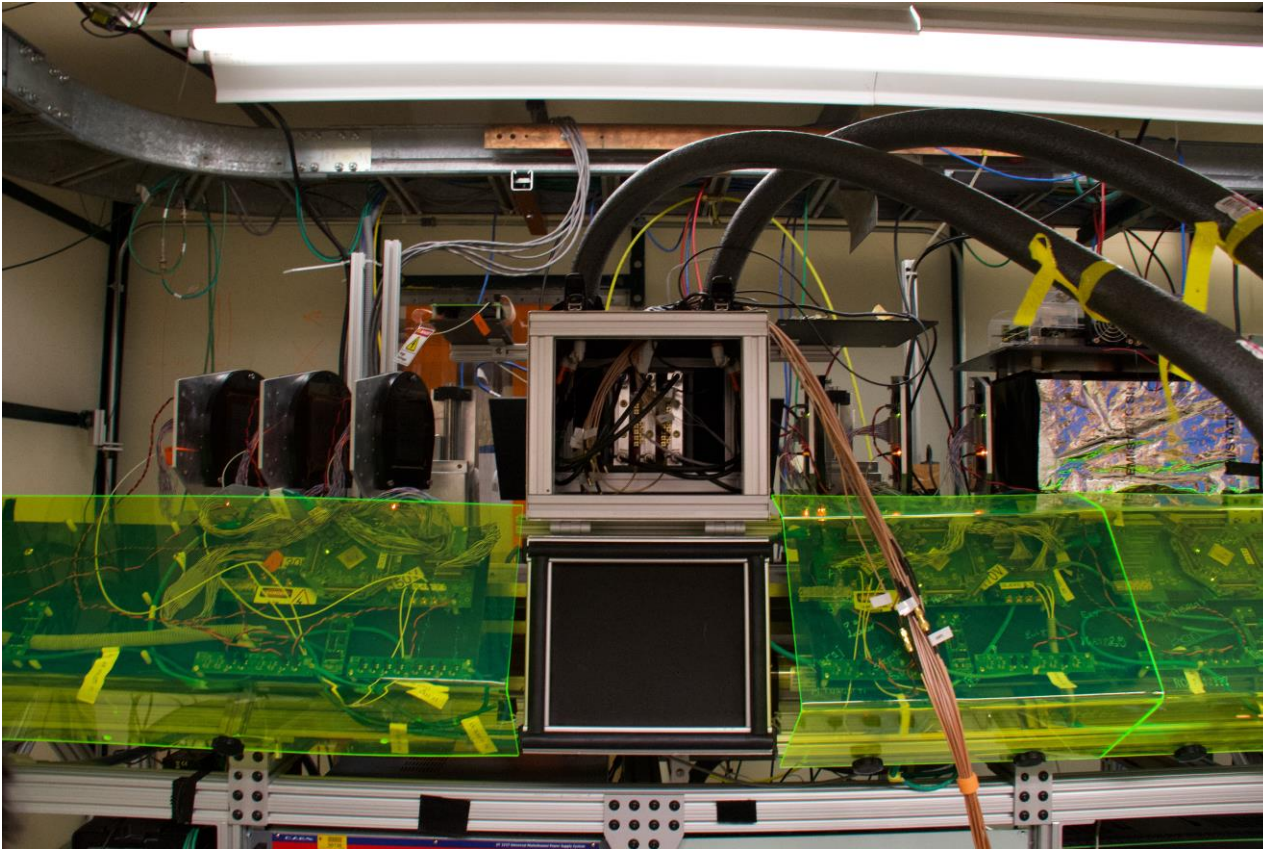
5 layer of Telescope  
 2 upstr. + 3 downstr.  
 (25μm x 500μm pixel)  
 Scintillator + MPPC trigger  
 Region of interest (ROI)

# Timing resolution for AC-LGAD detector

## Fermilab Test Beam Facility (FTBF)

120GeV proton beam

Strip Detector based Telescope :  $\sim 15\mu\text{m}$  pointing resolution



## Timing reference Detector

PHOTEK MCP photomultipliers (PMT140)

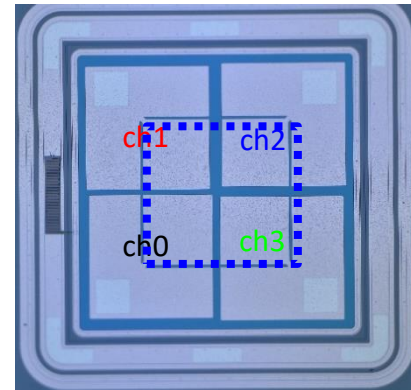
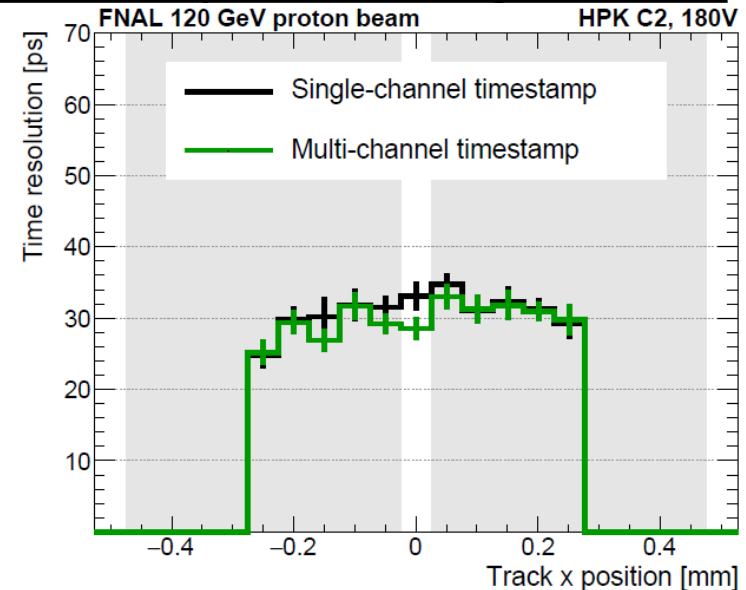
450ps FWHM with  $5e3$  Gain

**$\sim 5\text{ps}$  timing resolution**

**(SPEC: Multi-photon jitter below 10 ps)**



## Position dependent Timing resolution



- $25\text{-}35\text{ ps}$  timing resolution uniformly!**